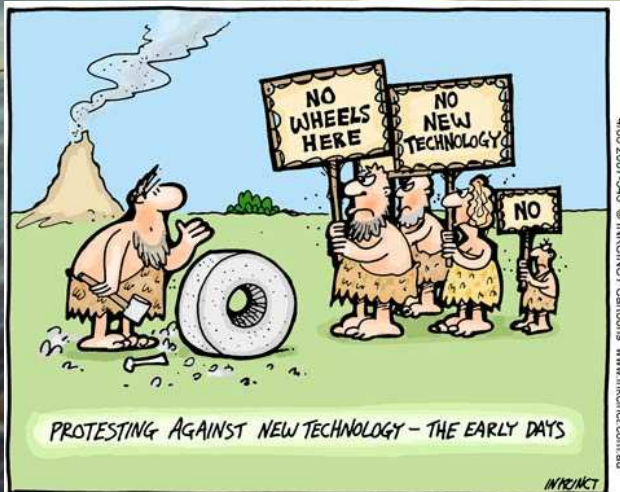


By Franck CADOUX, University of GENEVA



A quick view on some current Detectors & an Overview towards the Upgrades...

Supported by:

HAMAMATSU
PHOTON IS OUR BUSINESS

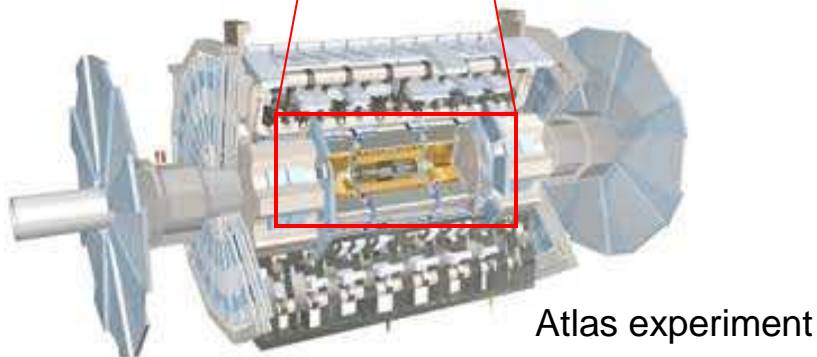
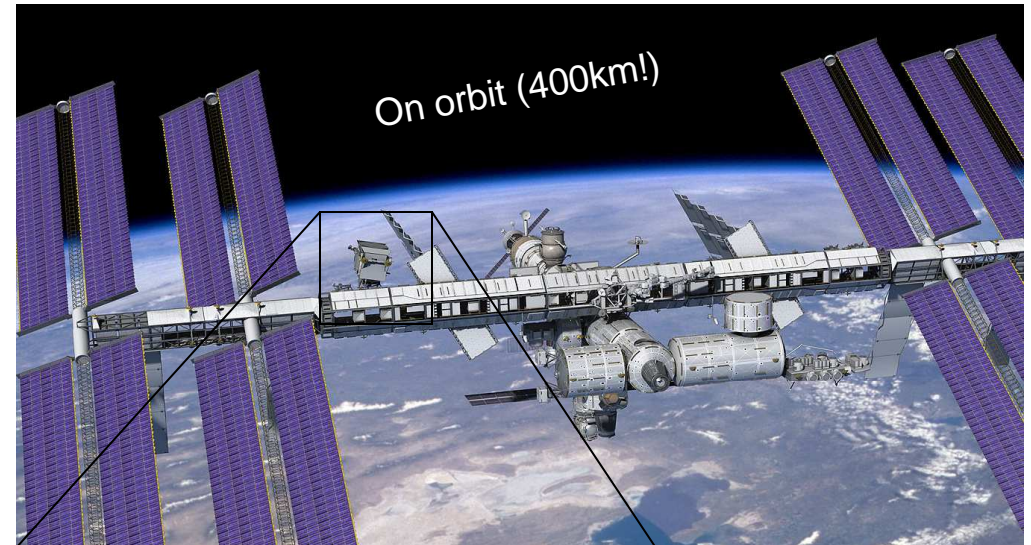
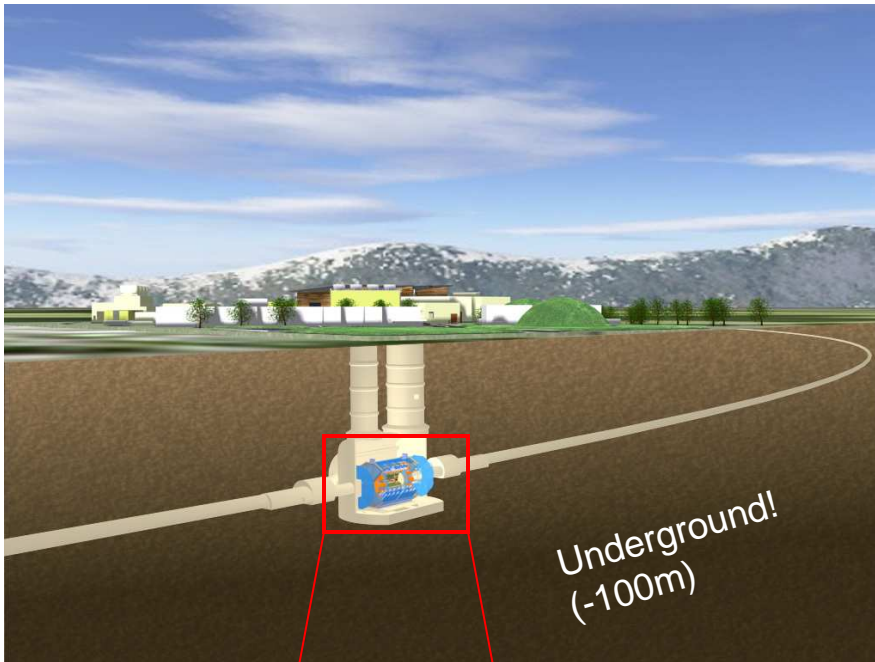


➤ Let's start with a feedback on **2 different cases** on current Trackers: ATLAS, AMS-02... non exhaustive!



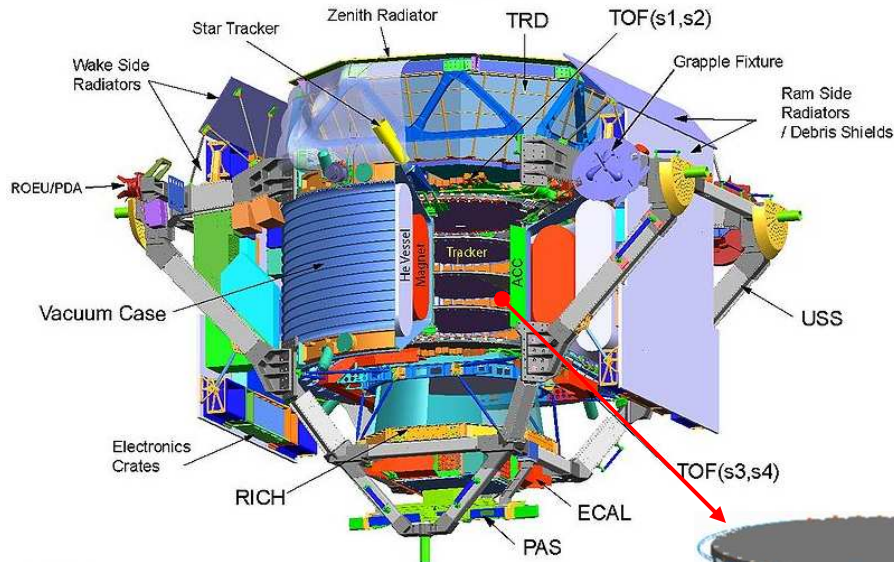
Highlight on **Atlas SCT**
(collaboration with UNIGE)

UNIGE on the **AMS Tracker**
Design & Assembly



- **AMS-02 Tracker** started in early 1999, following experience on AMS-01
- Re use of most of the technique from AMS-01 (silicon ladder), except the cooling system (TTCS)
- Different steps to get to the final AMS-02 configuration (very late change of the Magnet)
- Environmental constraints due to Space shuttle (logistics) and ISS location (site of experiment)

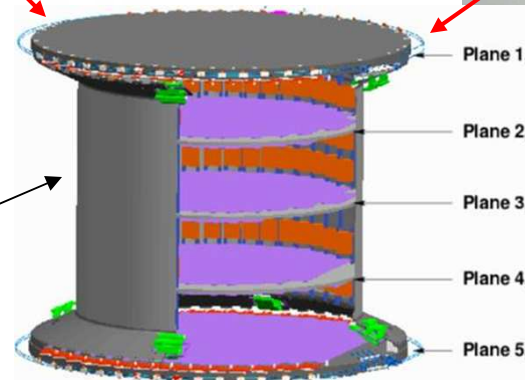
Simplified model of AMS-02 (stacking of TRD, Tracker, Tof, RICH, and ECAL)



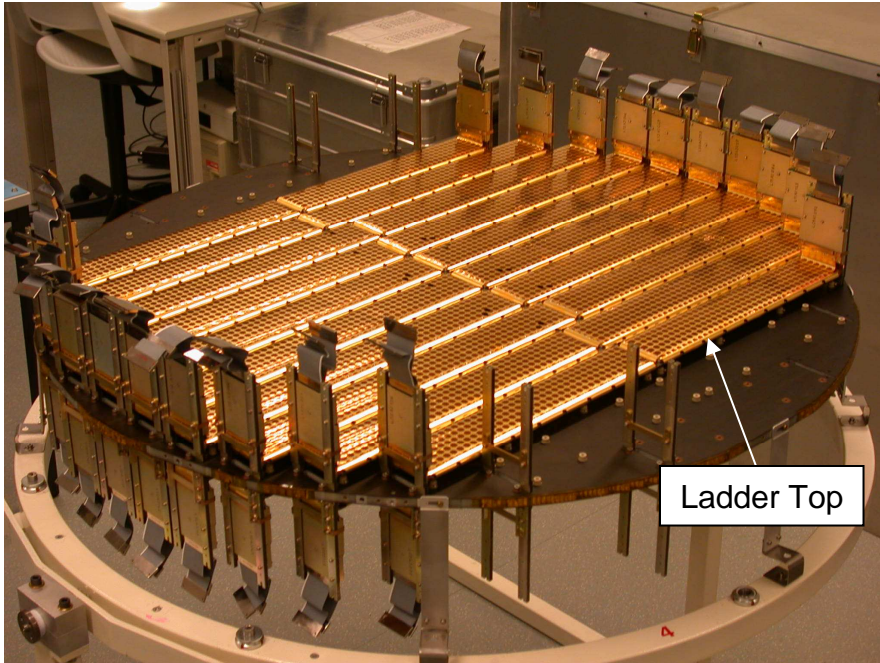
As it was in the clean room @ CERN... since 2007



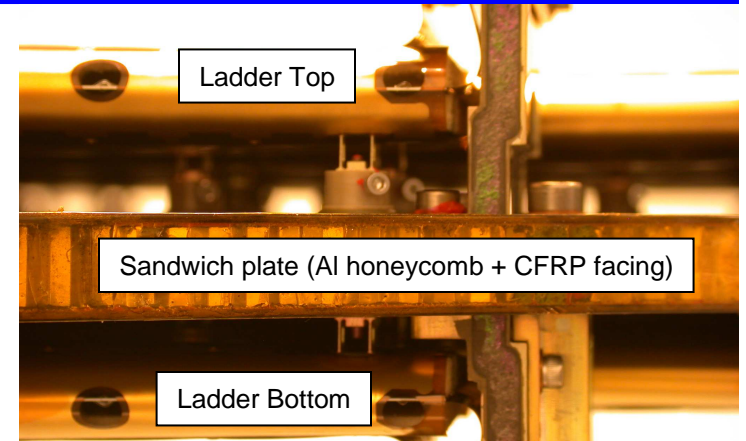
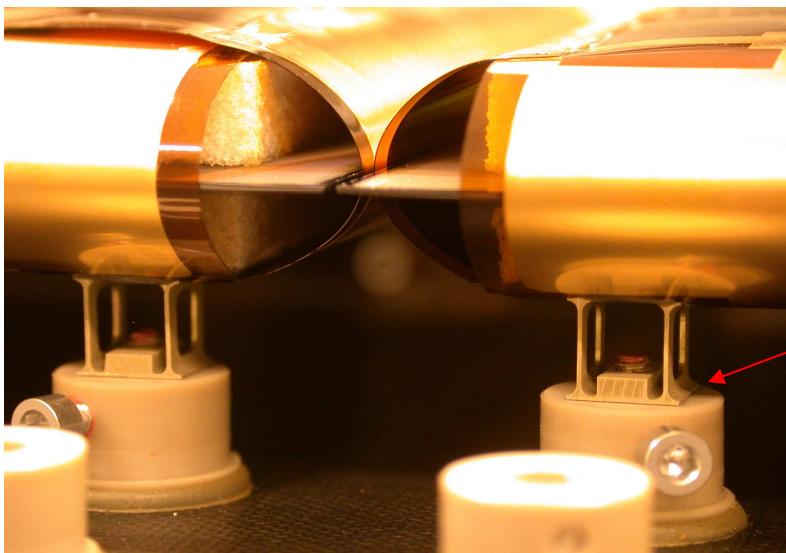
AMS Tracker as foreseen until 2009



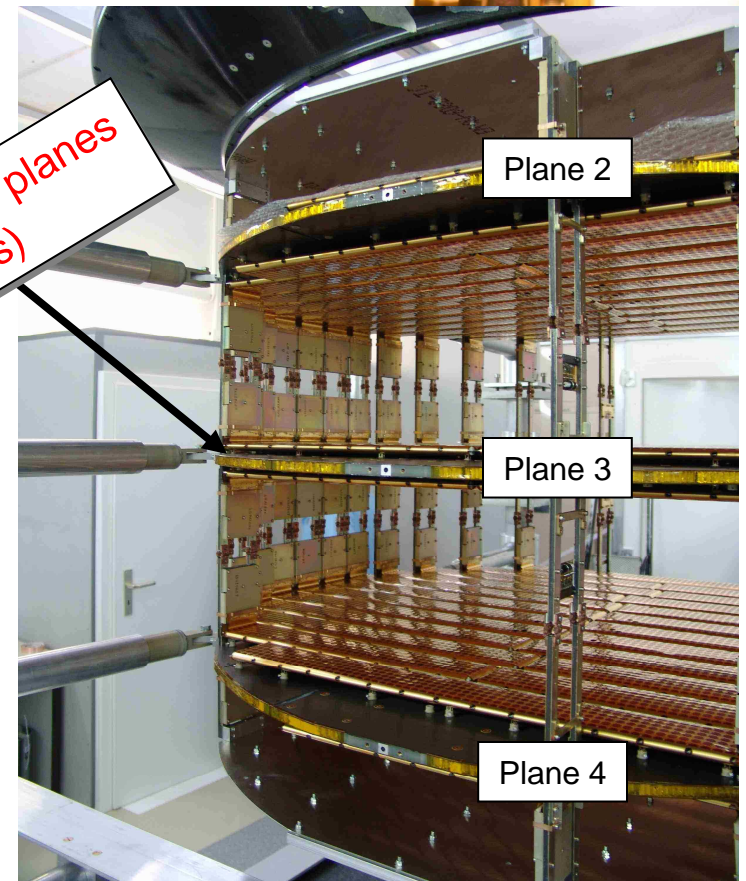
➤ Overview on 1 **Plane** fully equipped with Silicon ladders



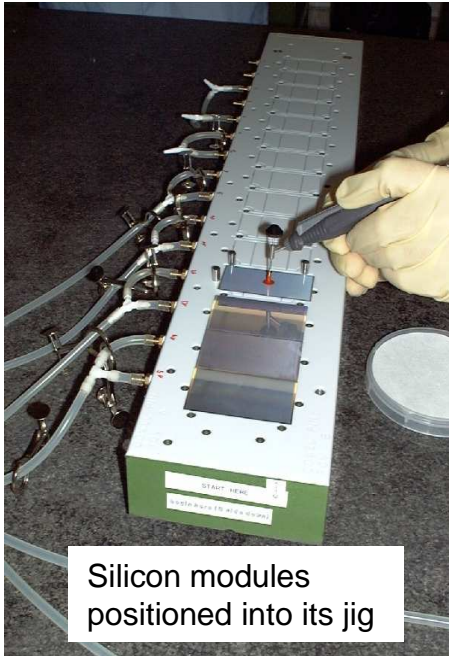
Connection between silicon ladder and honeycomb plate



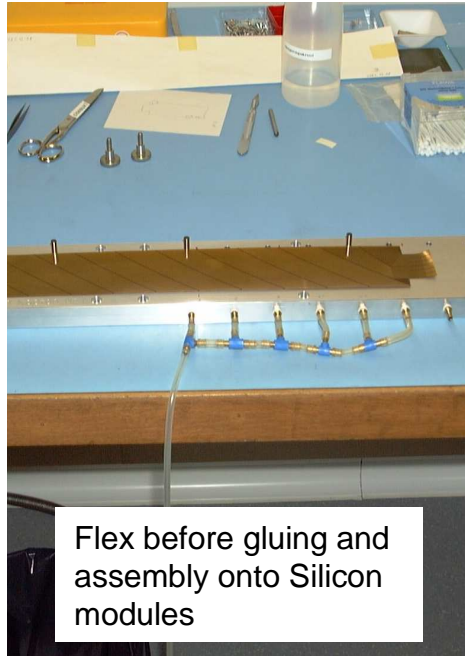
Reuse of AMS-01 planes
(with adaptations)



➤ Overview on the different **assembly steps** to get to the “Ladder” (precision achieved by jigs, controlled by CMM)



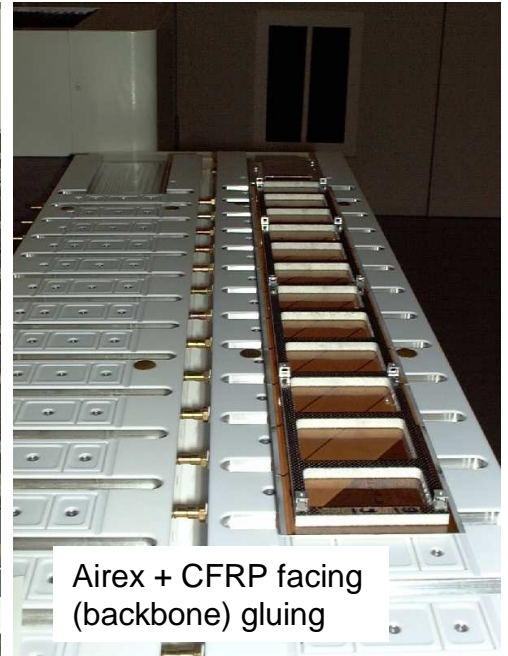
Silicon modules positioned into its jig



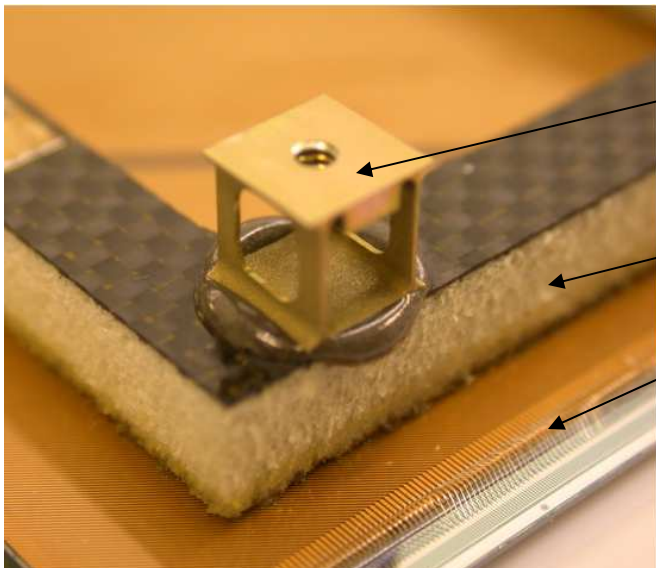
Flex before gluing and assembly onto Silicon modules



Flex + Jig reversed onto the modules for gluing

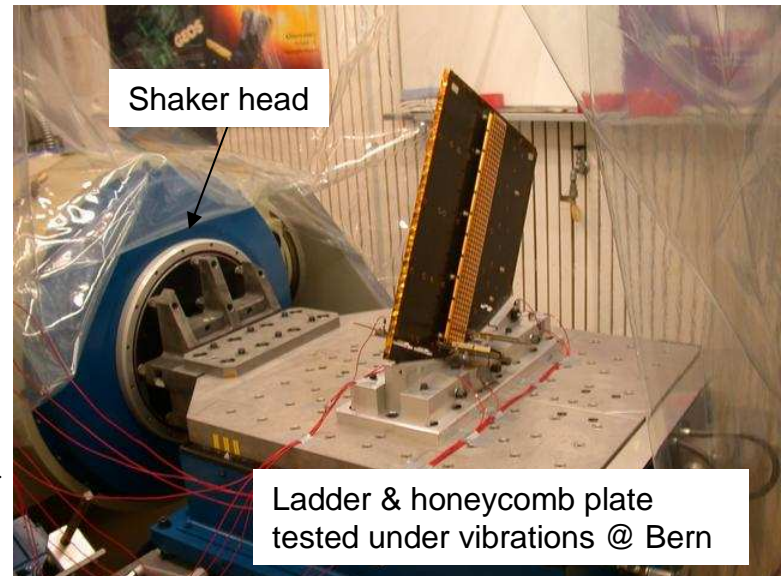


Airex + CFRP facing (backbone) gluing



Ladder Foot (aluminum 7075, by Electro erosion)
Airex foam + CFRP (space qualified)
Wire bonds

To be qualified by tests...

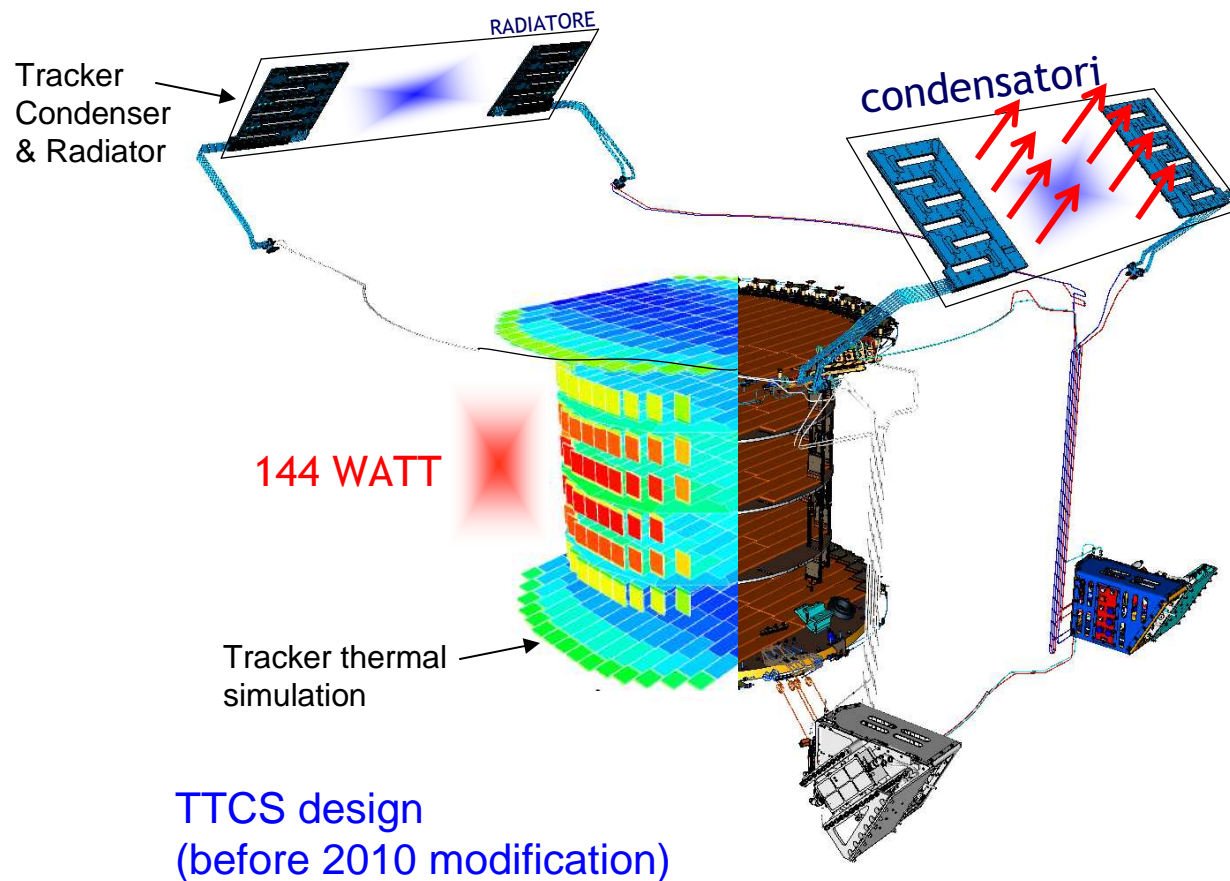


Shaker head

Ladder & honeycomb plate tested under vibrations @ Bern

One of the key part: The TTCS (Cooling system)

- AMS-01 was a passive cooling system (use of Permanent Magnet thermal inertia)
- AMS-02 Tracker designed with active cooling system (CO₂ coolant)
- System designed for Space (QA documentations “as thick as the detector itself”, welding checks,...)
- Redundant approach as required by NASA (2 lines A and B)
- 150 Watts to be dissipated, Temperature stable within 3°C over orbits
- 2 Phases Accumulator Controlled Loop (2PACL) as developed by NICKHEF

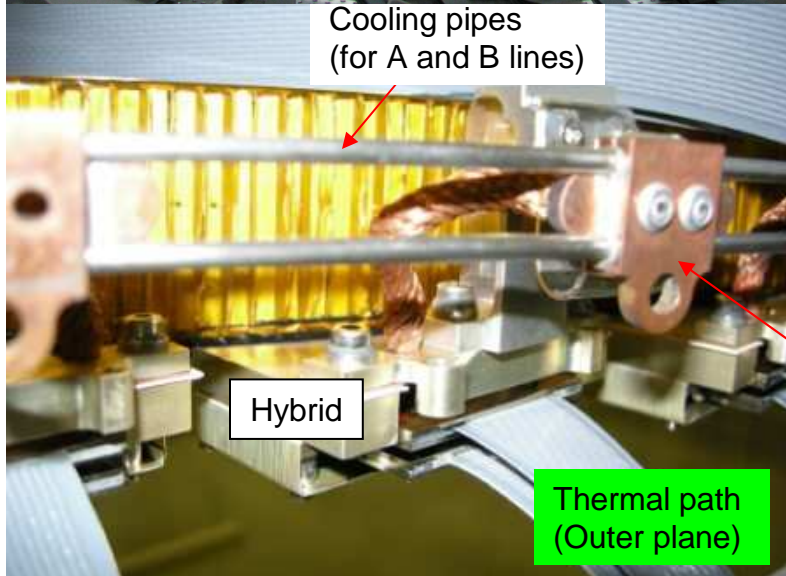
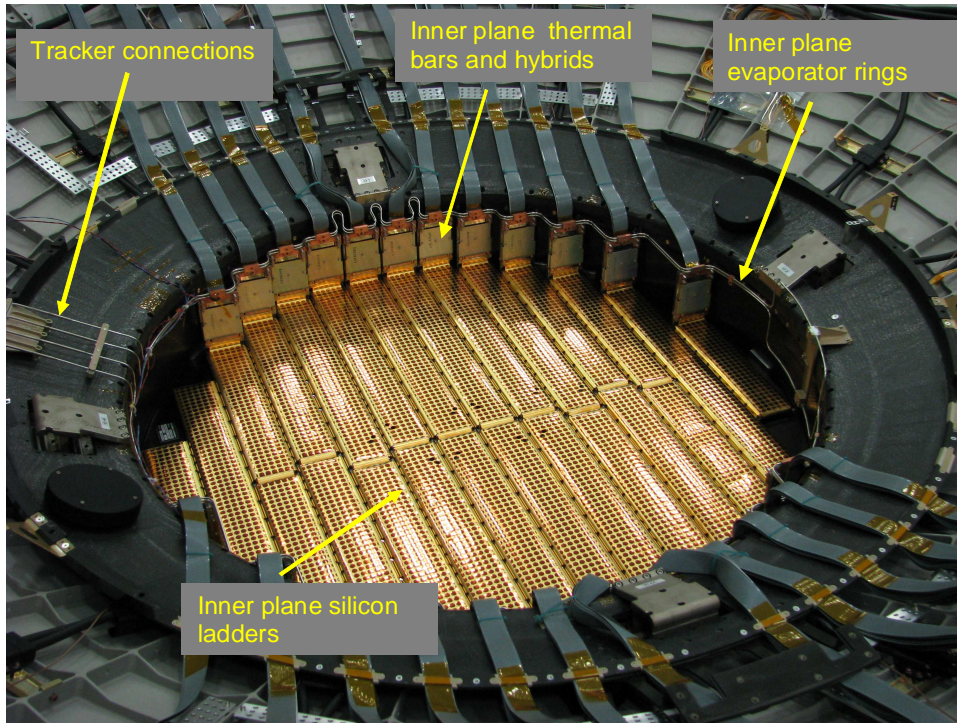


TTCS design
(before 2010 modification)



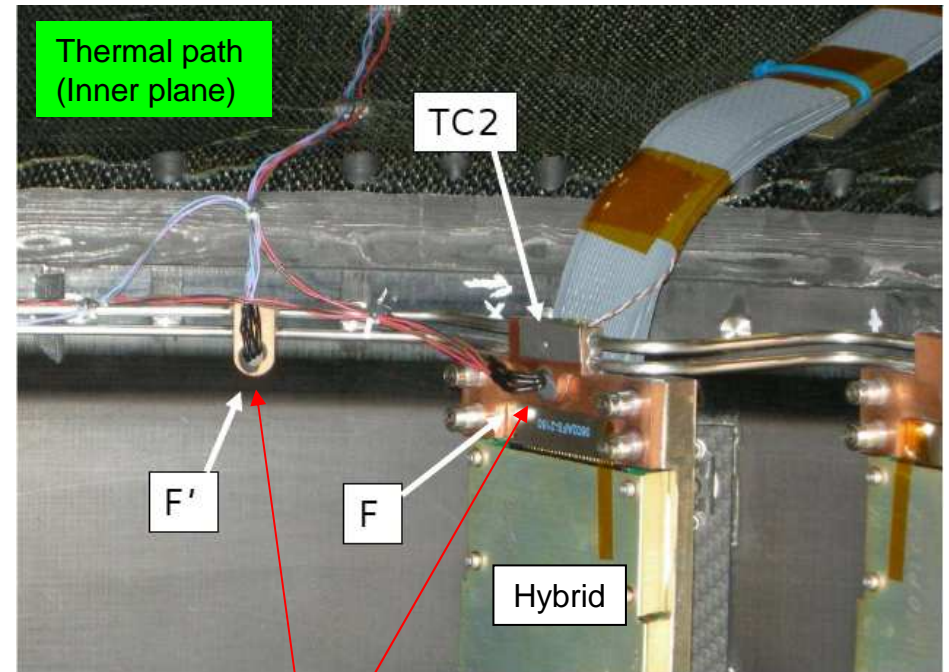
NASA Paper work...





Thermal block

- Orbital welding used in TTCS for every connector
- Cooling loops tested up to 250 bars (MoS)
- TTCS fully tested @ ESTEC late in the Integration (can only work under vacuum!)
- so far...IT WORKS PERFECTLY on the ISS !!



Thermal sensor all the way long...

The tricky equation...

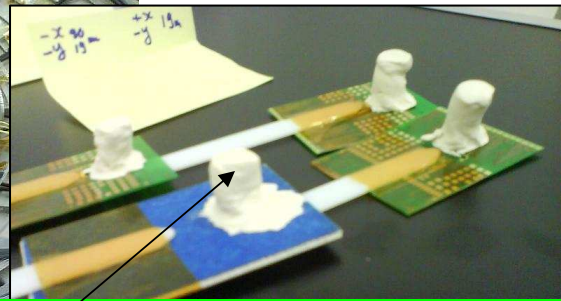
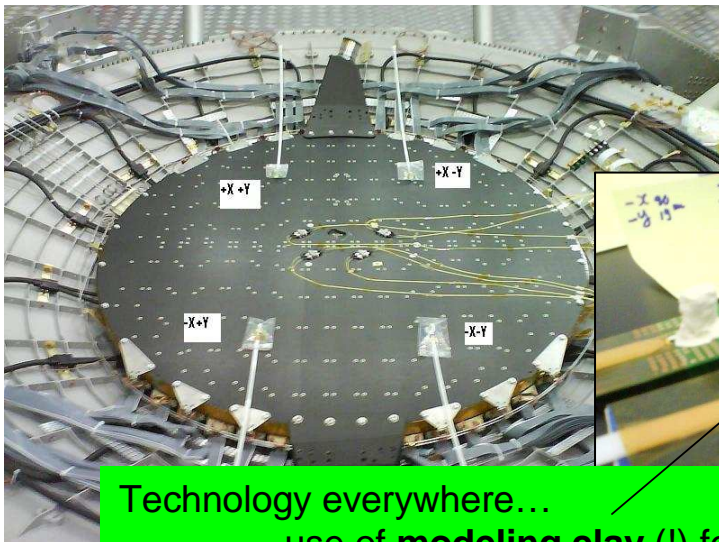
- Tracker Assembled at **1G**, not different from experiment on ground...
- But, Launched into space at **6G**...
- To finally end up at **0G** !!!...when Thermo cycling starts!

... But it's not an issue since the 6G load will drive the design anyway!

And tends to oversize things (margin of safety) even if 1 plane is estimated at **0,65% X/X₀**

- As a consequence, **FEA method** and **Testing** are mandatory in this field
- New technologies are welcome...but "new materials" are "suspicious"
(NASA qualification process among aging, out gassing, ...)

No way back in case of failure...
Full system to be secured at every steps!
Some similarities on Atlas



Technology everywhere...

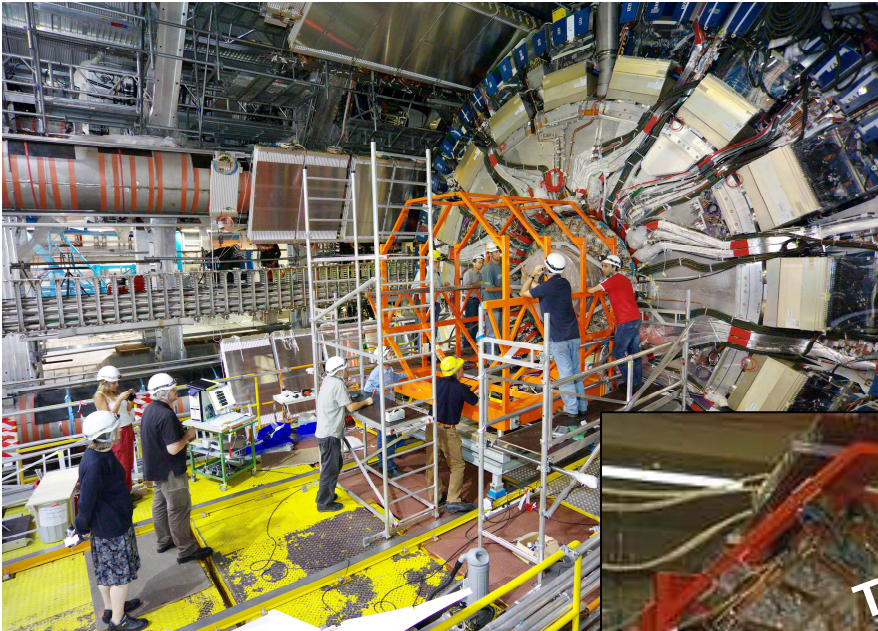
use of **modeling clay** (!) for interference check (Tof vs Tracker)

**FAILURE
IS
NOT
AN
OPTION**

KENNEDY SPACE CENTER

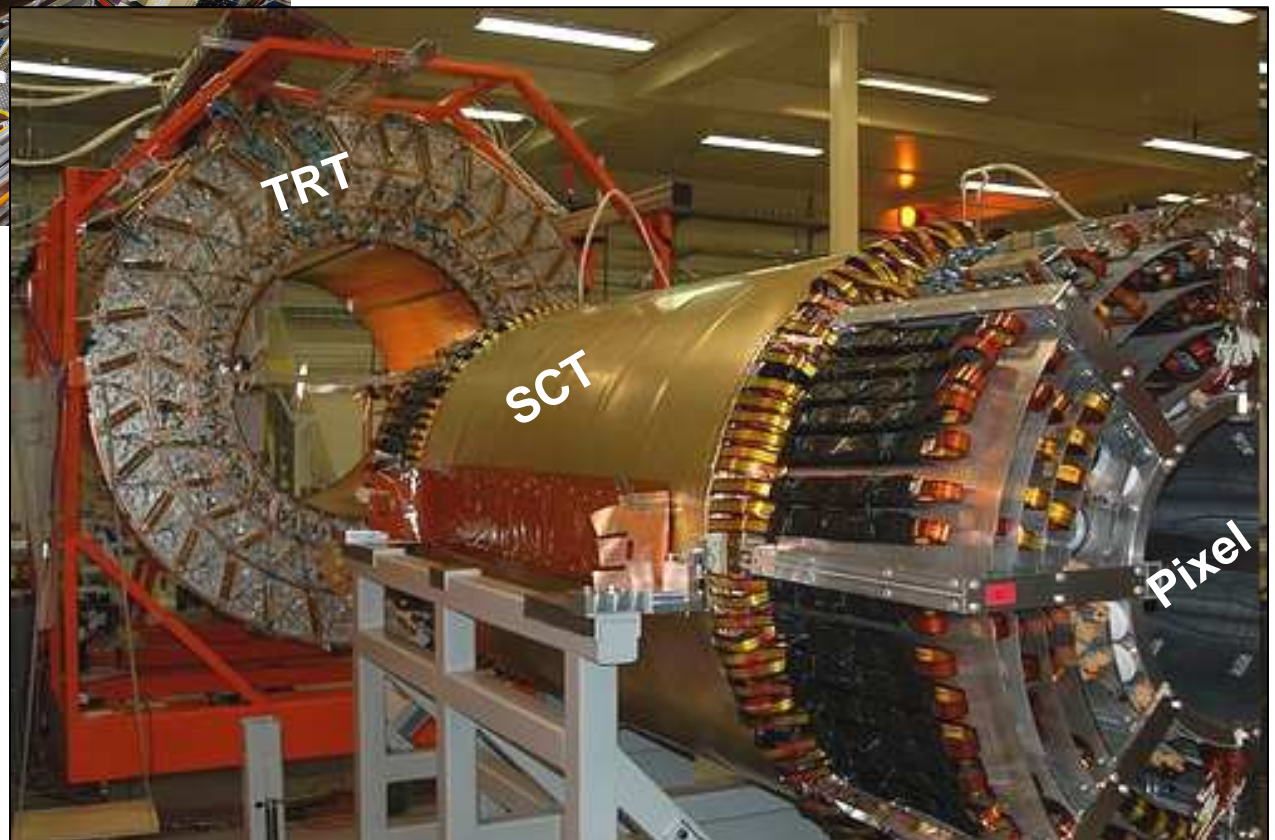


- Now let's move on to the ATLAS pit (about 100m underground...complete different environment, but with some similarities)

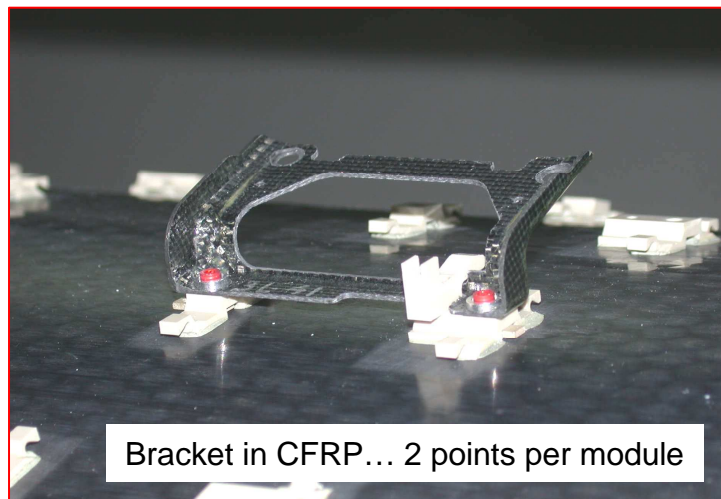
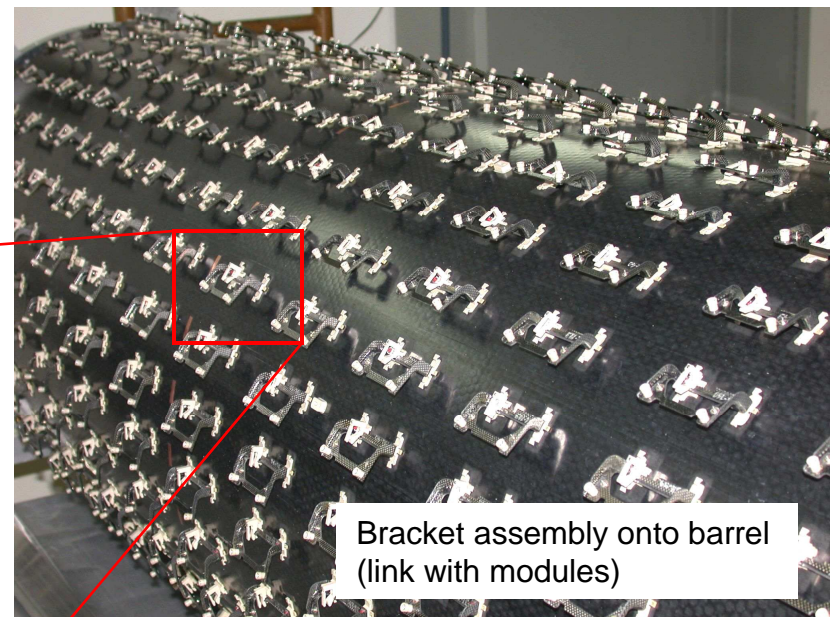
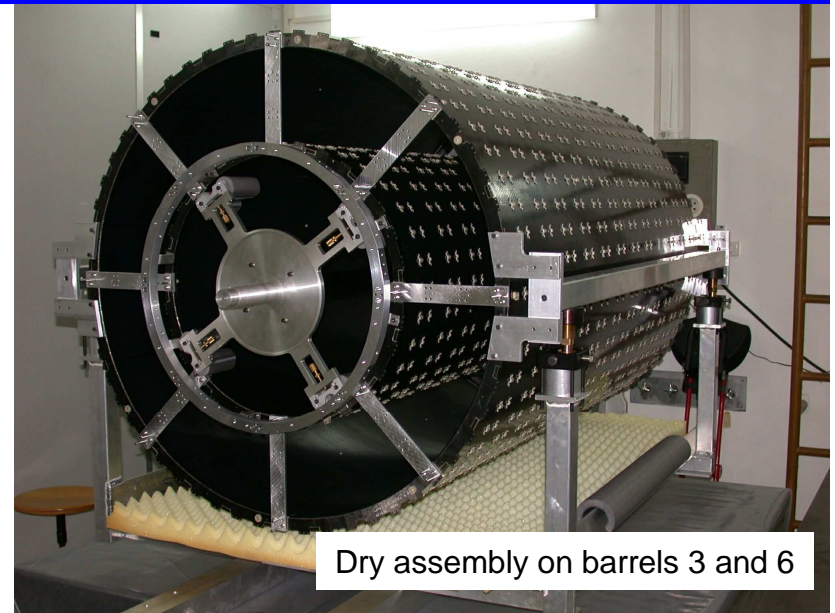
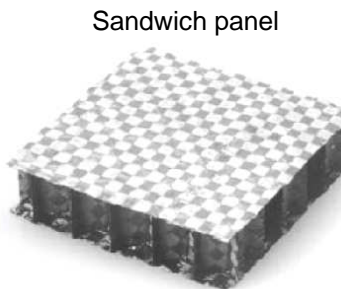
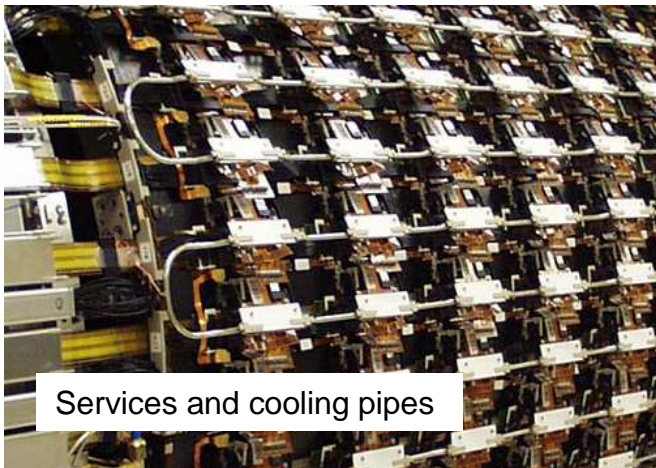


... with more focus on the **Barrel SCT**

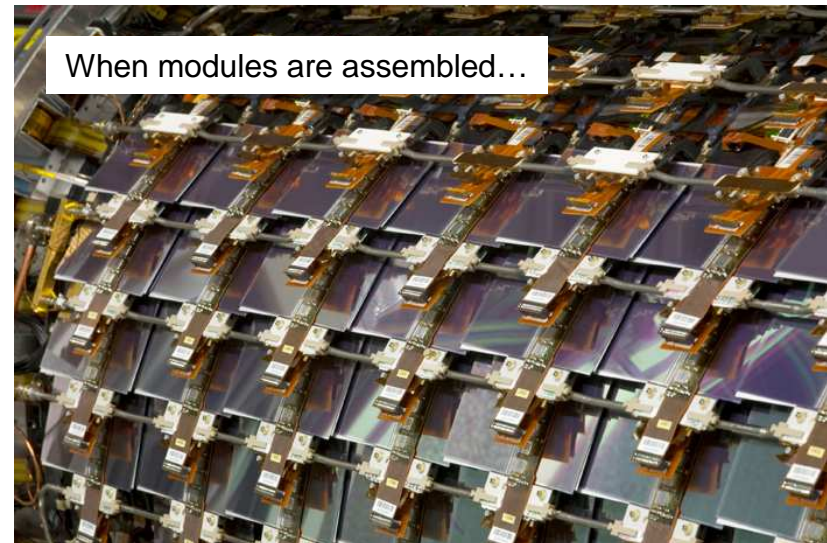
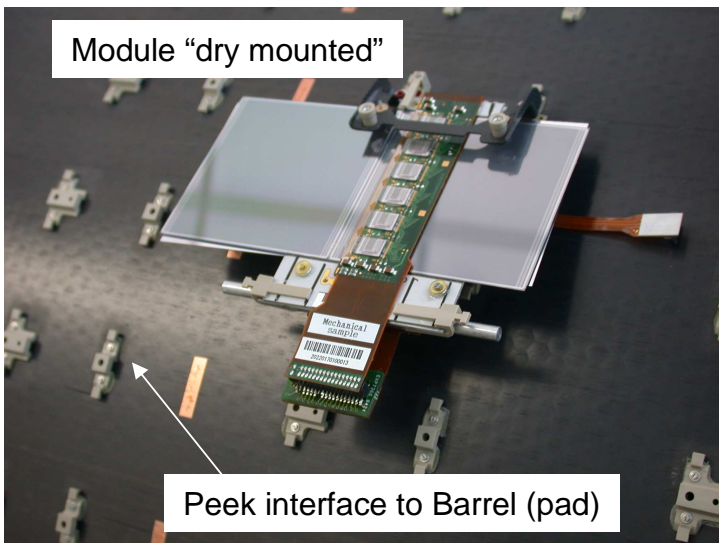
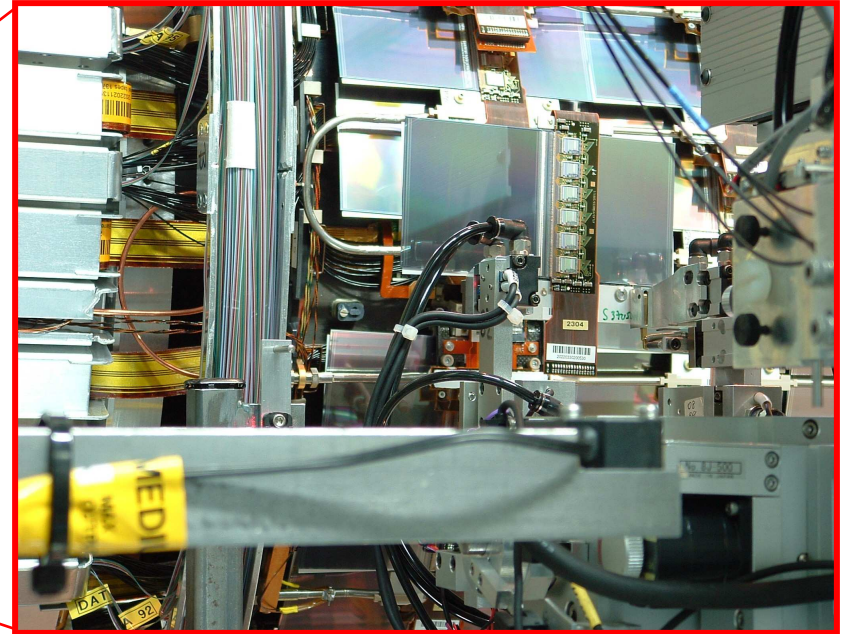
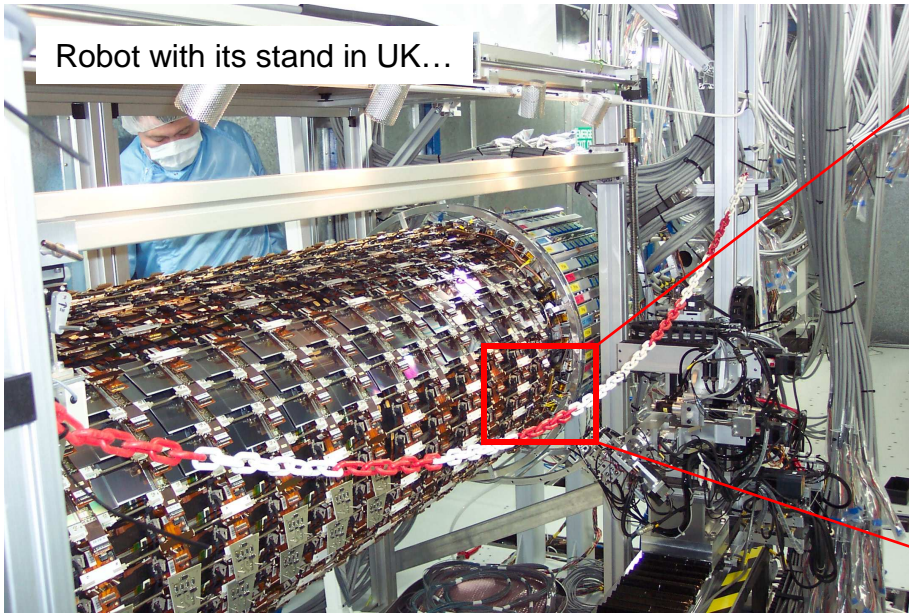
On behalf of the **Barrel SCT**
Engineering Team
(UNIGE within a large
collaboration)



- **4 Concentric barrels** connected with 8 Interlinks (Sandwich structure, XN50/RS3 facing, core in honeycomb with the same fiber type)
- **Individual bracket** to hold modules (many links to barrels)
- **Services and Cooling** assembled onto the barrel prior module mounting



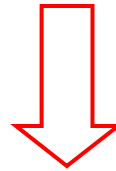
- **Module loading** done 1 by 1 on barrel (Robot developed by KEK and UK)
- **Barrel assembly** only AFTER MODULES ARE LOADED AND TESTED



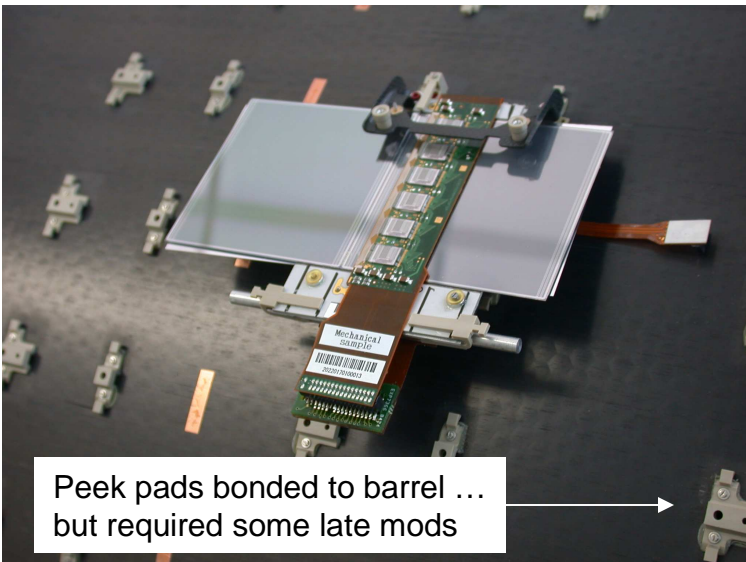
Technical assessment... and Feedback



- Use of such honeycomb panel exhibited very **good stability!**
- ...and **very light structure!** Could be pushed still more.... but risky!
- **Mounting precision** achieved by Barrel machining (within 50 microns)
- The estimate of services early in the design was too optimistic (late changes made the optimization difficult!)
- Better use an **integrated CAD model** (Cabling, cooling, electronics, ...)
- Such long barrel are **difficult to re machine** after lamination
- Some Peek pads de bonded at some step, and required a lot of rework

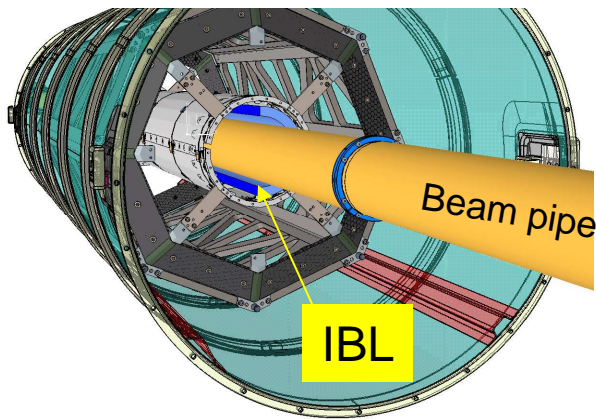


Towards the Upgrades!
Some new philosophies
inherited from the past
experiences...



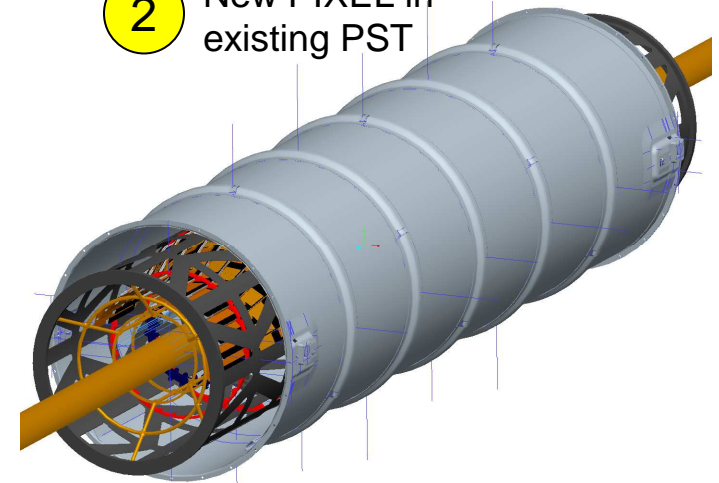
- Different steps in the Upgrades: IBL, PIXEL in 2017, and the rest in 202x...
- Try to summarize the new Ideas / Techniques developed among those projects

1 IBL in 2013 shutdown

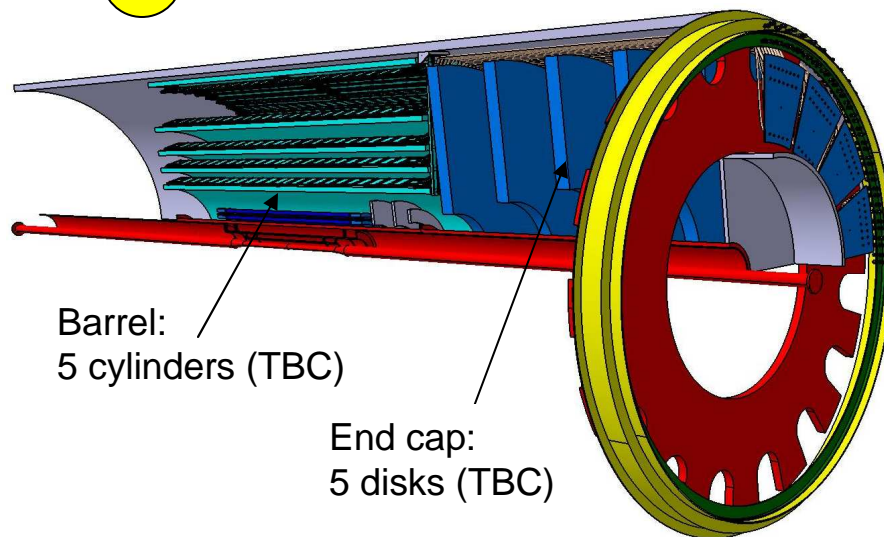


Pushing both mechanical and thermal performances to the limits...

2 New PIXEL in existing PST



3 Strips (Barrel+ End cap) in 202x



Common approach:
Service managements early in the project (use of CAD integrated tool)
...as part of the whole project!

➤ Overview on **IBL developments** (what are the challenges...?)

Try to insert "something" (or some sensors...) in between Beam pipe and Pixel layer 1
... in term of figures: $ID\ 55mm < IBL < OD\ 85mm$... over 7300 mm long!

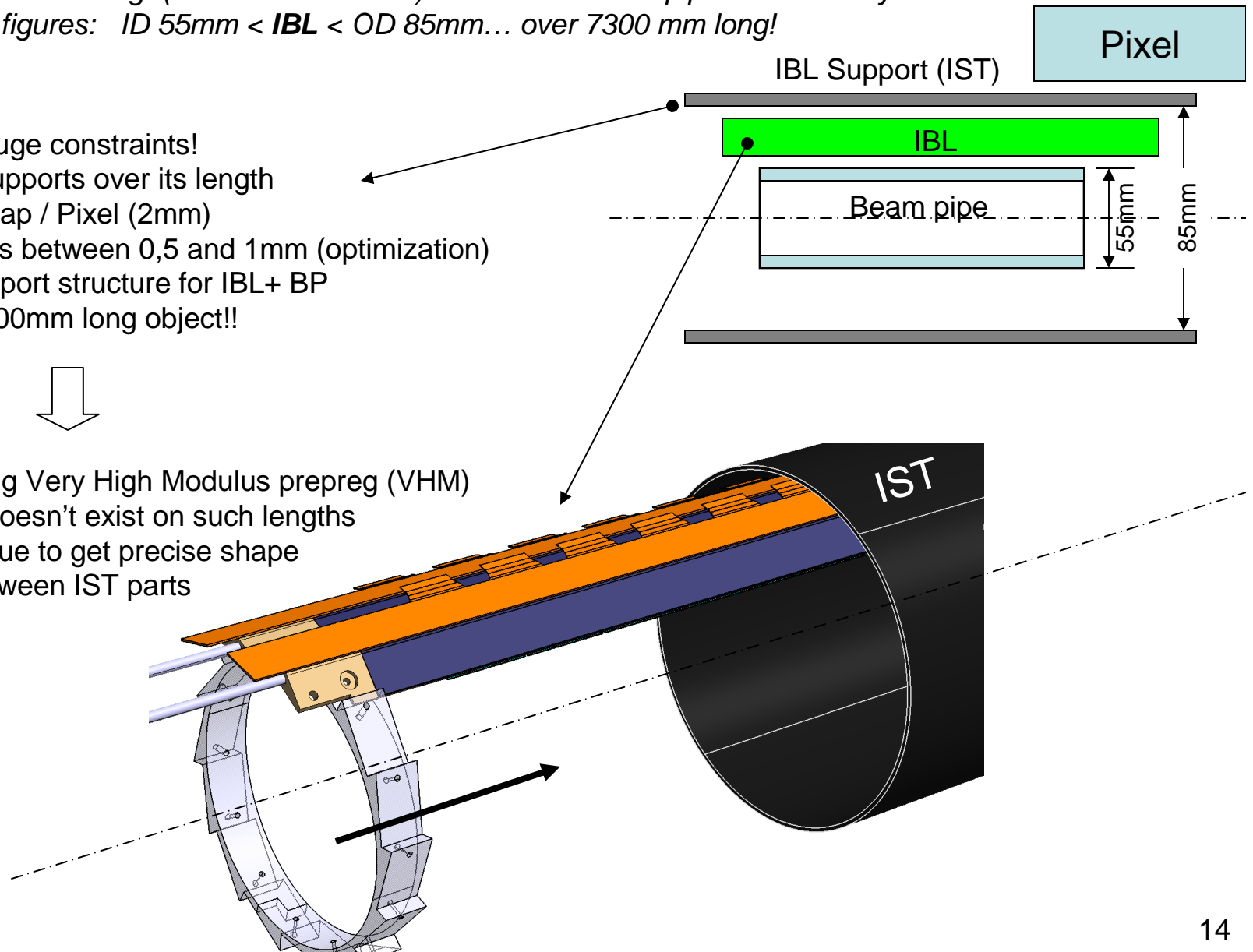
For **IST**, huge constraints!

- Only 4 supports over its length
- Limited gap / Pixel (2mm)
- Thickness between 0,5 and 1 mm (optimization)
- Main support structure for IBL+ BP
- Get a 6600mm long object!!



R&D using Very High Modulus prepreg (VHM)

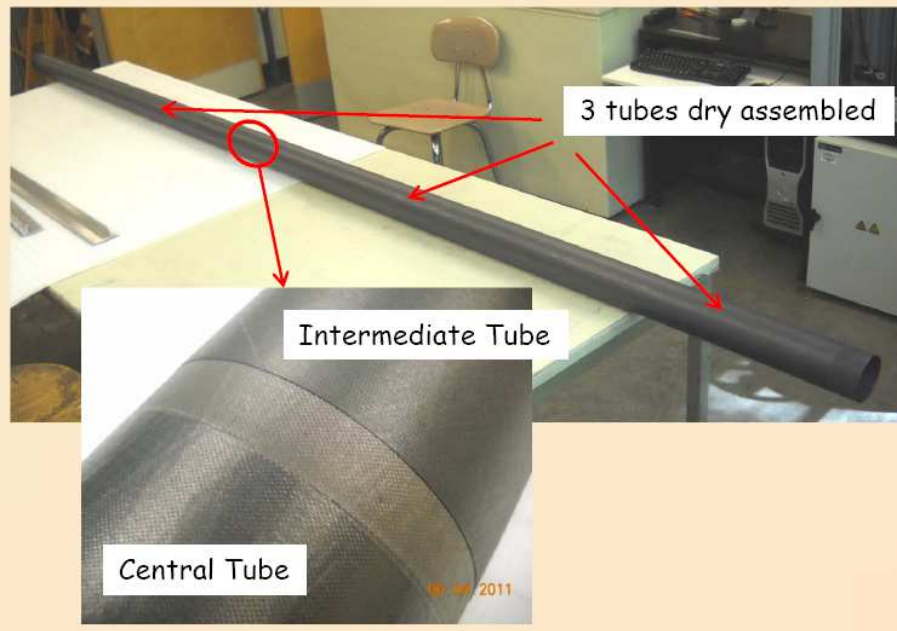
- Tubes doesn't exist on such lengths
- Technique to get precise shape
- Link between IST parts



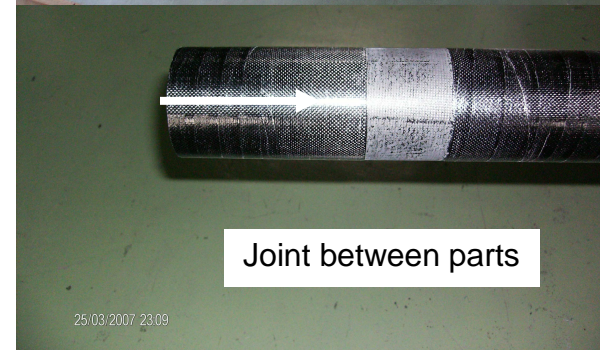
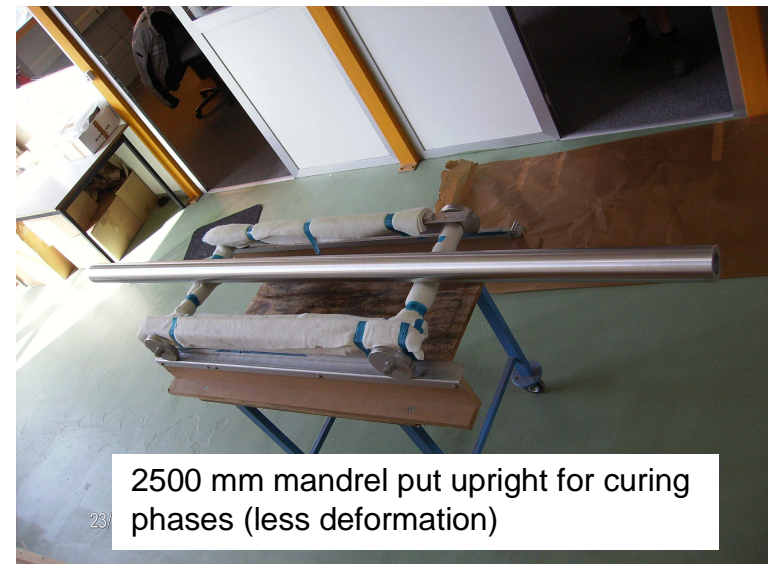


➤ IST development in parallel in **Seattle** and **Lausanne**

- Using K13C/RS3 prepreg (VHM)
- Optimization of the lay up (number of layers, and their orientation)
- Include an outer mesh for shielding
- Could potentially see high temperatures (BP bake out) ...resin chosen accordingly



- Using T300 woven prepreg
- Aluminum mandrel
- Cured in vertical position



- A work is being done with CERN EN/MME, to check the structural behavior on a prototype...and correlation with FEA
 - Eigen value search
 - And Modal shape analysis

CERN — European Organization for Nuclear Research			
EN	EN/MME Laboratoire de Mesures Mécaniques / Mechanical Measurement lab Rapport expérimental / Investigation report		
	Author: Raül Morón Ballester	Date: 28/04/2011	EDMS Nr : 1139623
Customer: -CERN	Approved by : M. Guinchard		
Distribution list:			
Experimental modal analysis of a carbon tube for a satellite			



CFRP pipe hanging from the roof with elastic ropes (free-free conditions)

- 2 accelerometers
- Smart hammer shock (mapping)

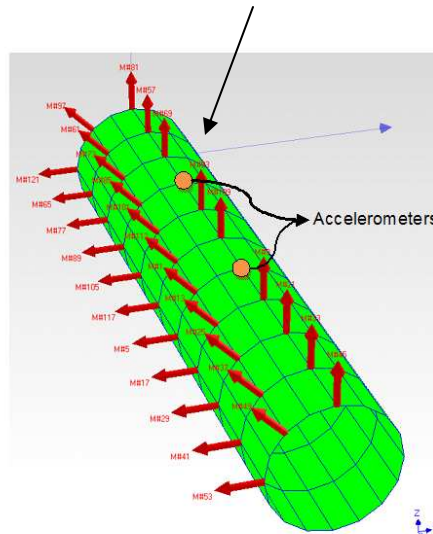
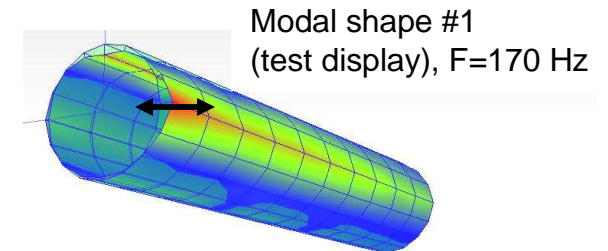


Figure 1: Model of the tube with the grid, the impact points (arrows) and the accelerometers position

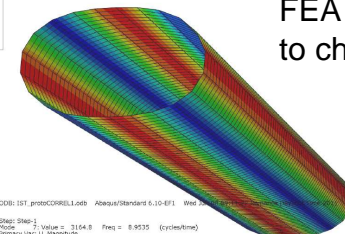
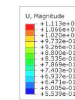
Results from Tests...

Mode	Frequency (Hz)	Damping (Hz)	Damping (%)
1	170	2.95	1.73
2	176	2.52	1.43
3	274	3.44	1.26
4	579	2.85	0.493
5	731	2	0.273

Table 1: Modal parameters of the carbon tube



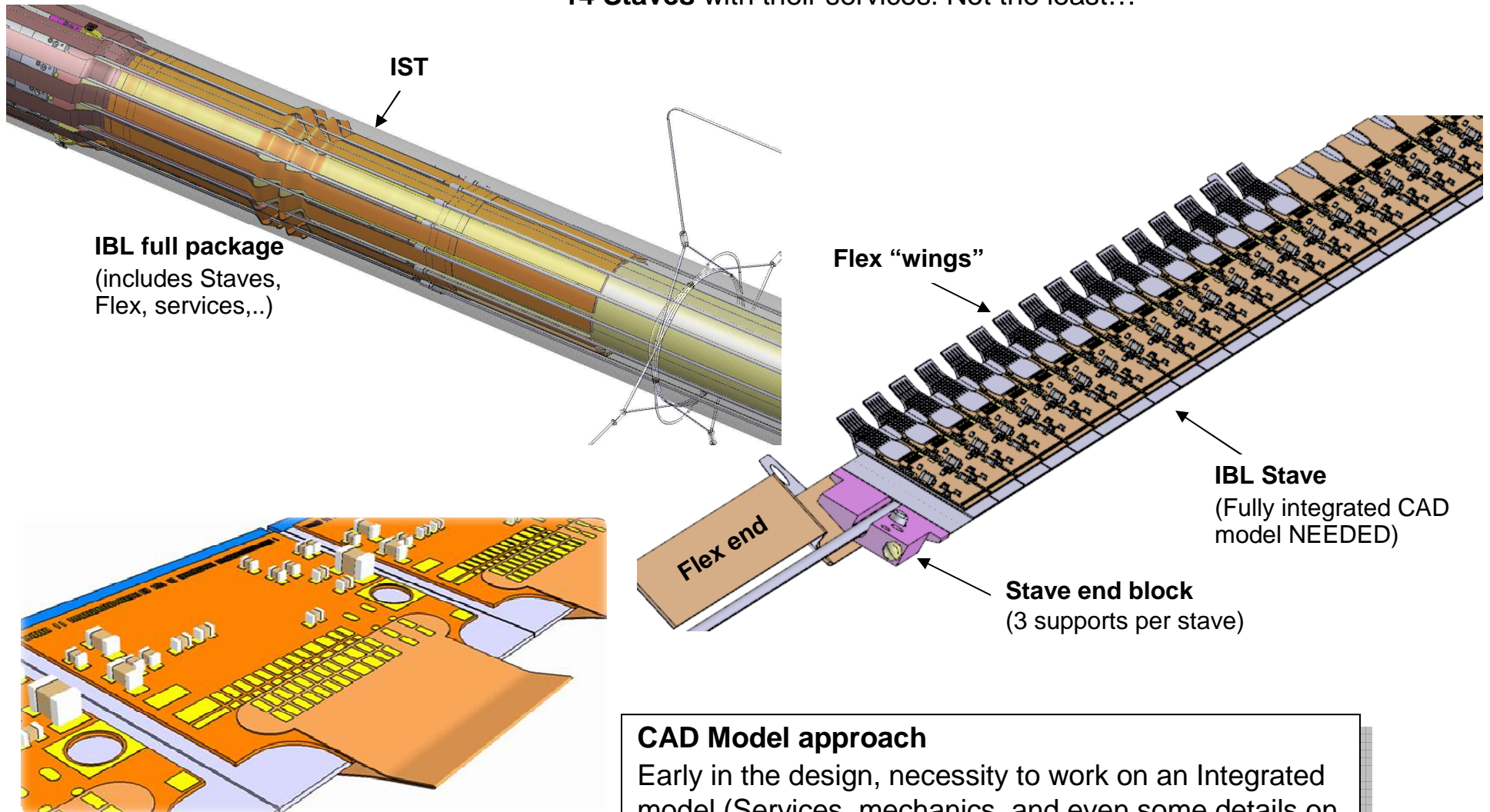
Modal shape #1 (test display), F=170 Hz



FEA results to check...

ODB: S11_protocORBELL1.odb Abaqus/Standard 6.10-EP1 Wed Jun 22 10:58:00 2011
Step: SIme-2 Value = 3164.9 Freq = 8.9533 (cycles/time)
Node: Primary var: U, Magnitude
Element: V1: U Definition: Scale Factor: *1.000e+01

- ... don't forget the "stuff" to be inserted thru the IST:
14 Staves with their services! Not the least...

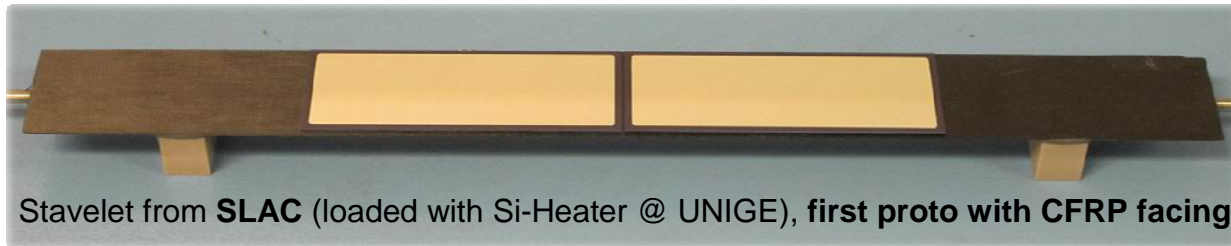


CAD Model approach

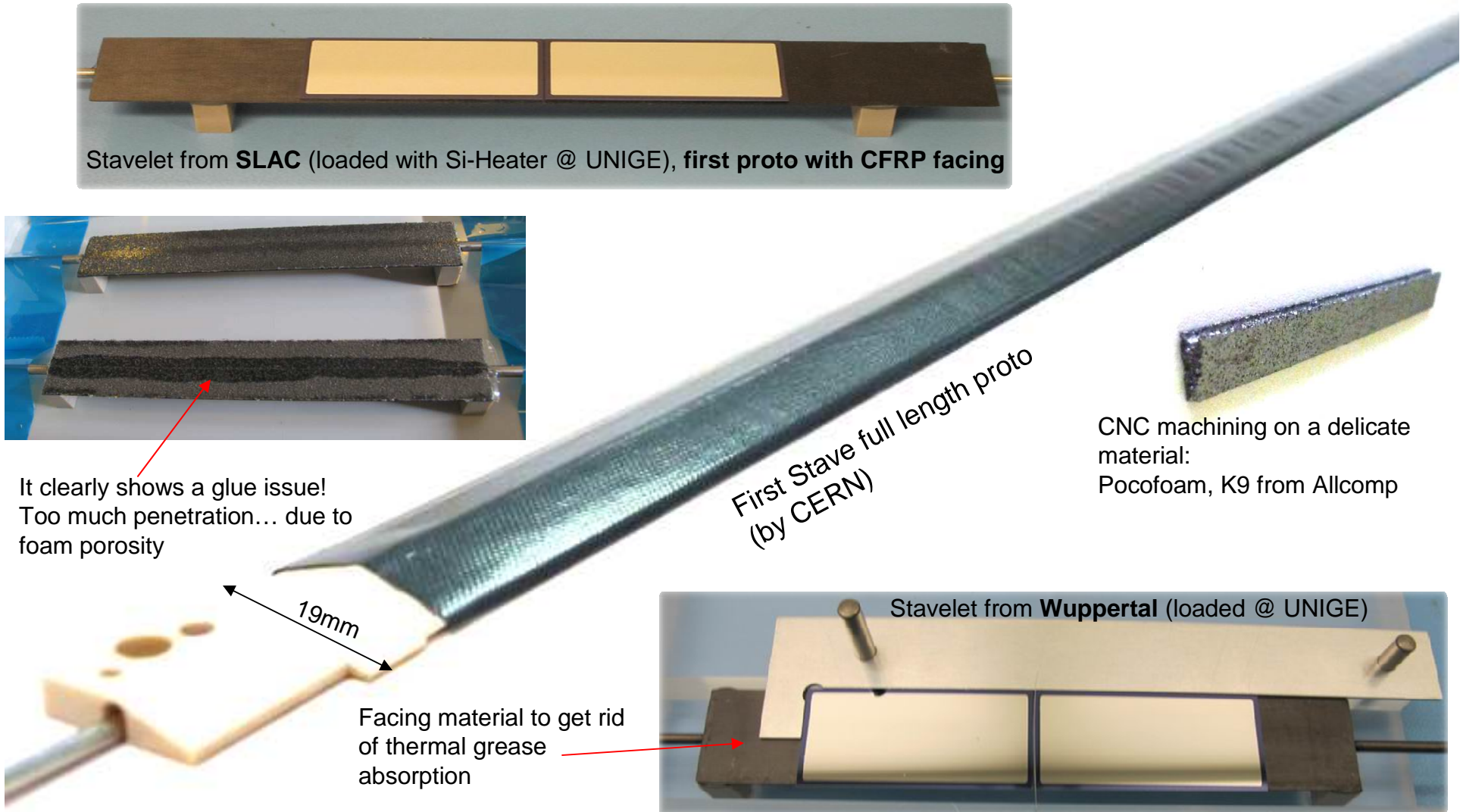
Early in the design, necessity to work on an Integrated model (Services, mechanics, and even some details on electronic components...).

- Due to short clearances on IBL!

- **Stave** development... in search for a light, stable, and thermally good object! Sort of **sandwich structure**
- Several stave prototypes by Wuppertal, CERN, SLAC to test:
 - Manufacturing processes (challenging)
 - Assembly techniques (co curing, re machining,...)
 - Options in term of facing material, foam type... Validated by FEA and Thermal Tests @ CPPM (Marseille)



It clearly shows a glue issue!
Too much penetration... due to
foam porosity



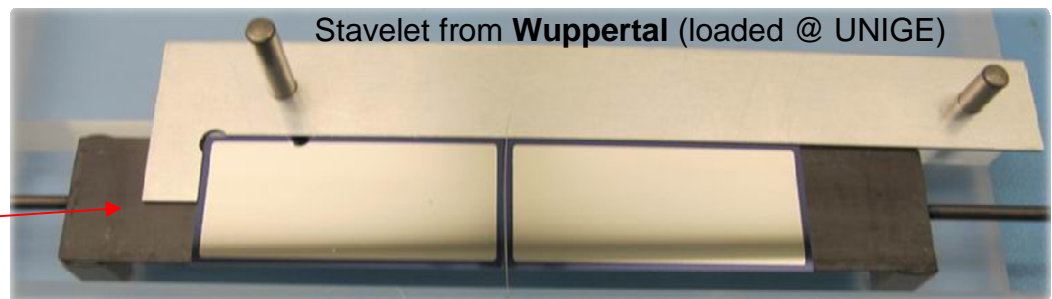
First Stave full length proto
(by CERN)



CNC machining on a delicate
material:
Pocofoam, K9 from Allcomp

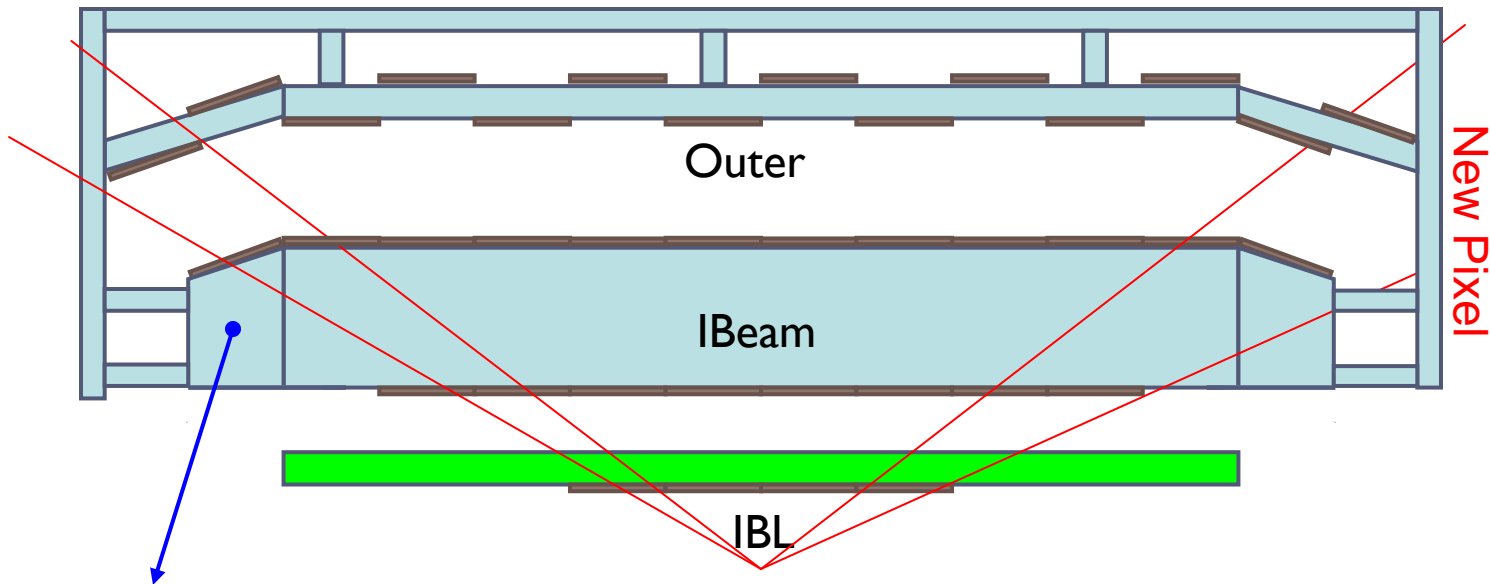
19mm

Facing material to get rid
of thermal grease
absorption

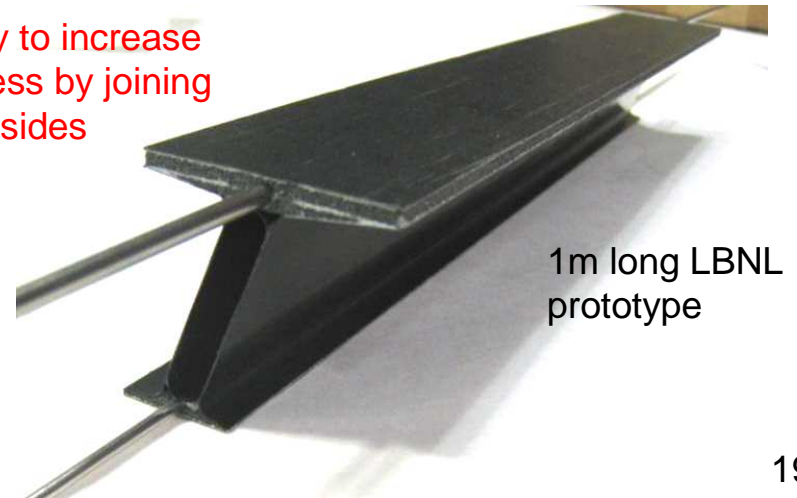
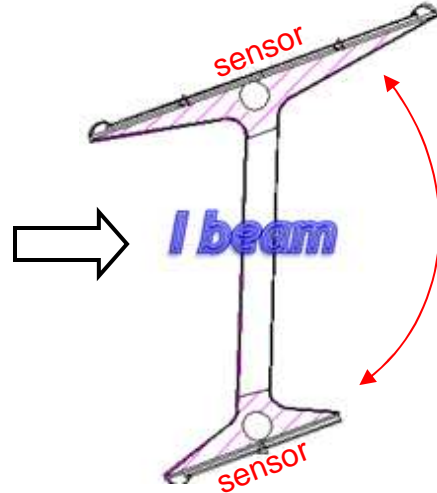
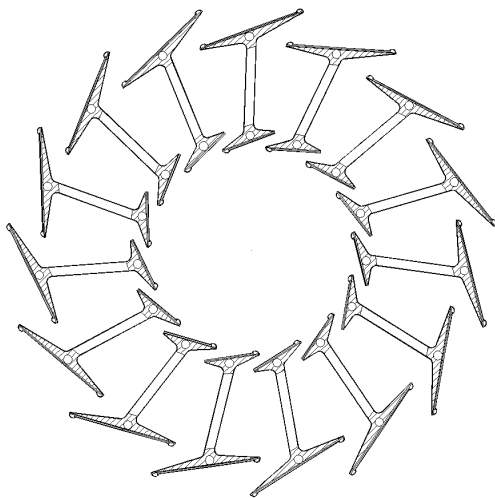


- An overview on **PIXEL** latest studies (for 2017 replacement). On behalf of **LBNL** group

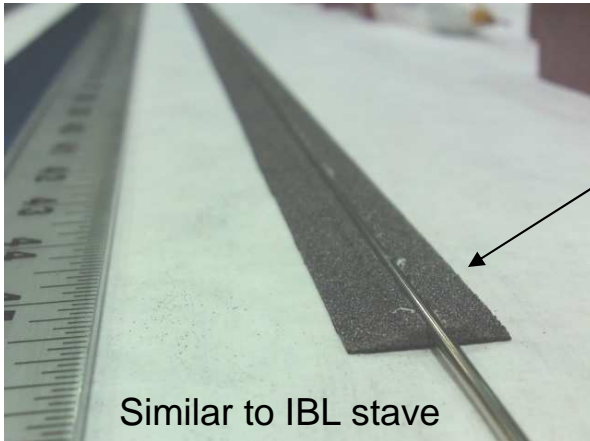
1 of the 3 layouts as proposed by N. Hartman in March 2011 (**No disks**)



- Focus on a self supporting structure: the “**I Beam**” conceptual approach (challenging)



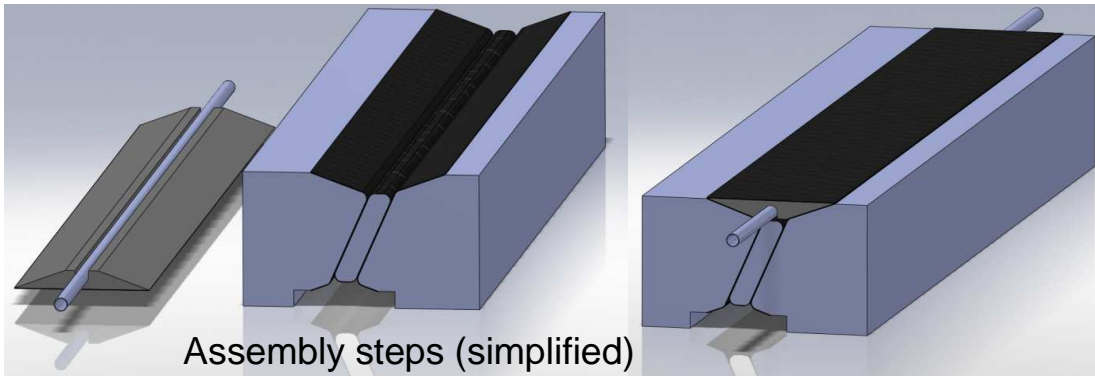
- Full length prototype manufacturing and FEA's



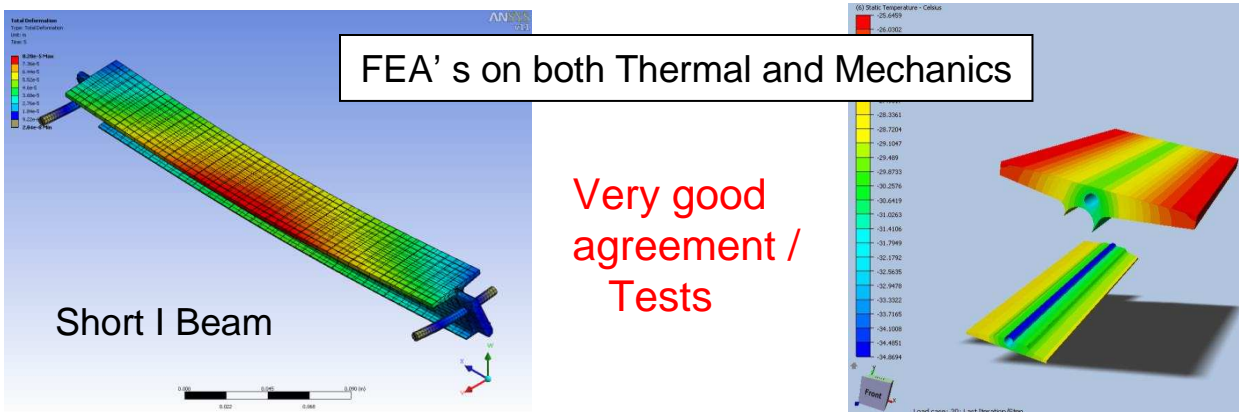
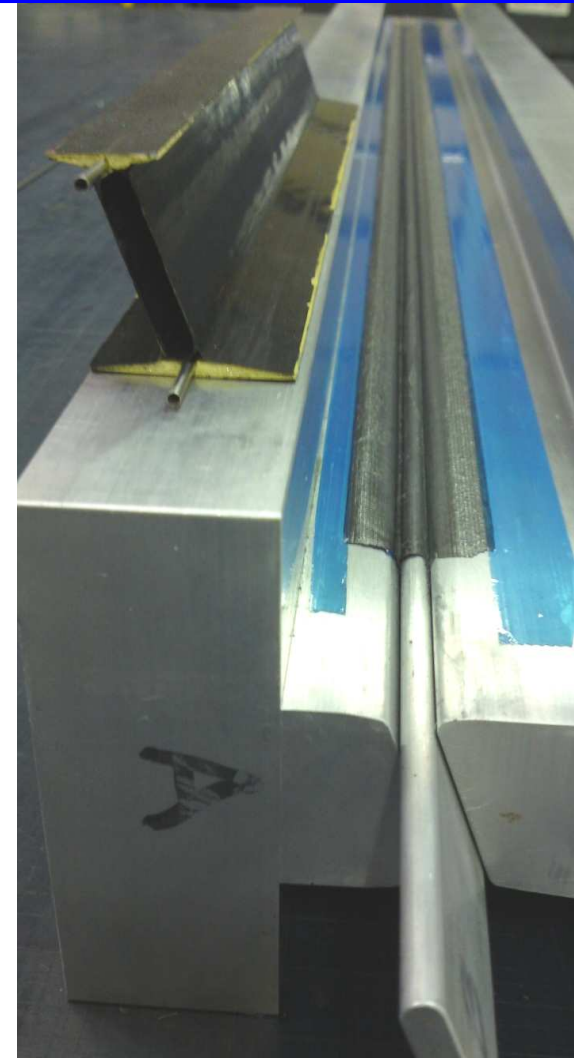
Similar to IBL stave

K9 low density foam (as for IBL, 40W/mK)
Laminates in M46J for proto
...changed into K13C (?)

We see a lot a complementary studies with IBL (mutual benefits)



Assembly steps (simplified)

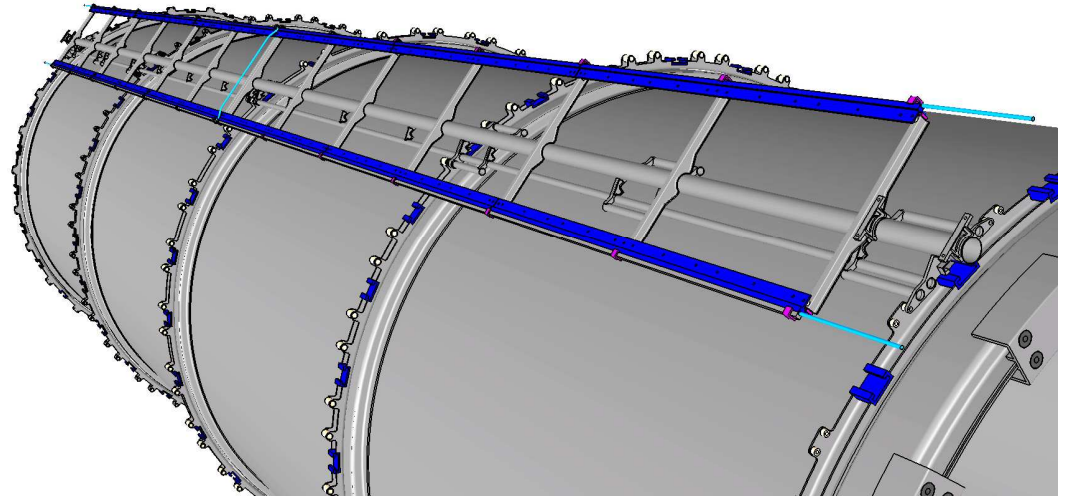
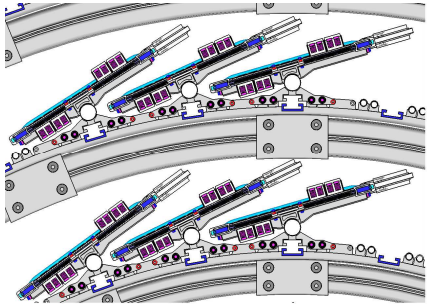


FEA' s on both Thermal and Mechanics

Very good agreement / Tests

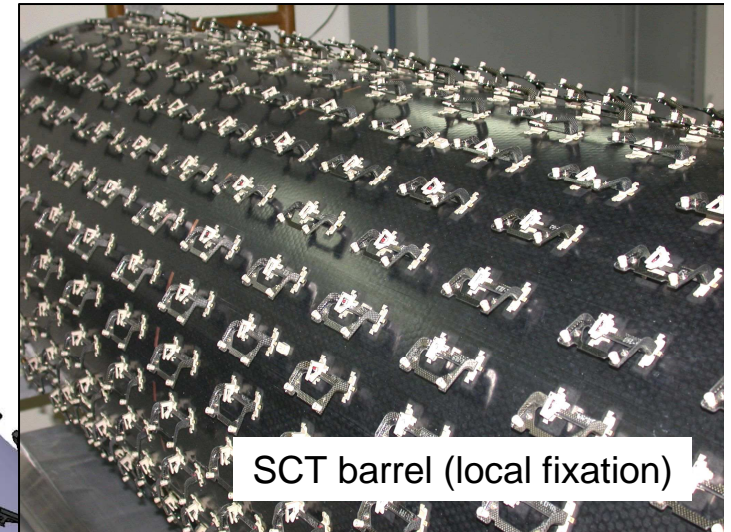
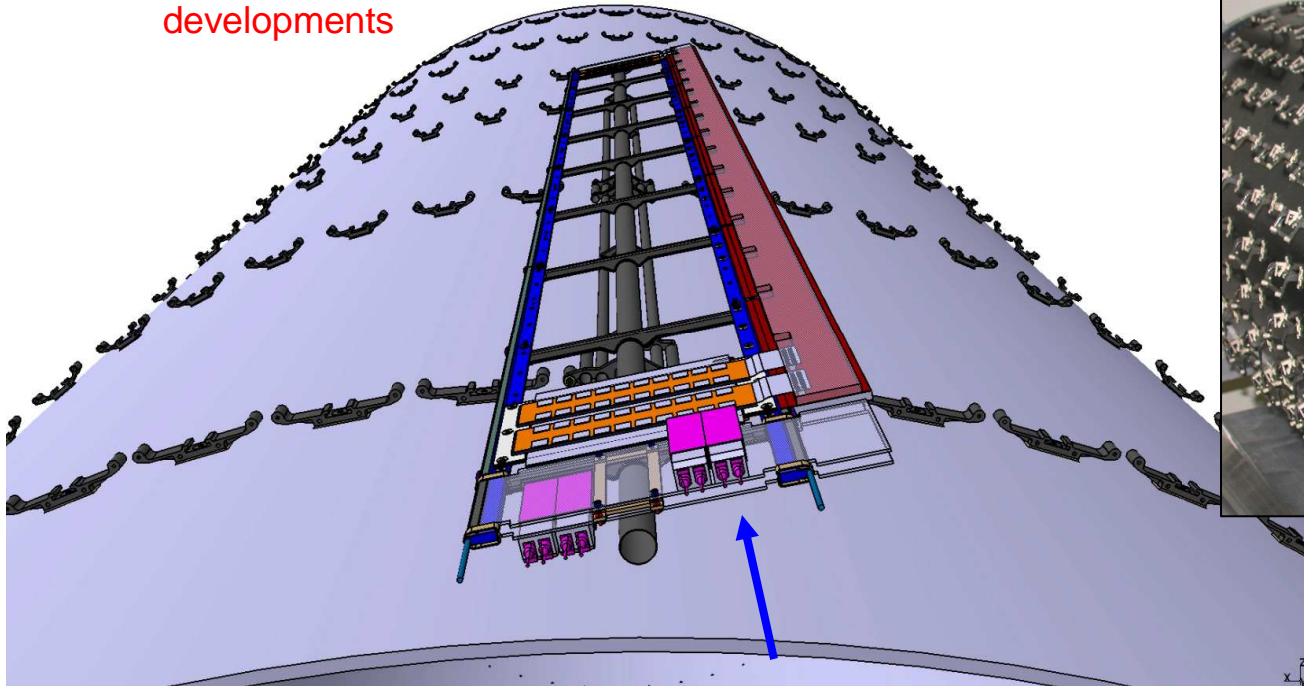
Next step is to work on I Beams integration and services

- and finally, for the outermost part...the developments on **STRIP** detector
There are a lot of approaches being designed, tested in parallel (Staves, SuperModules, Petals)



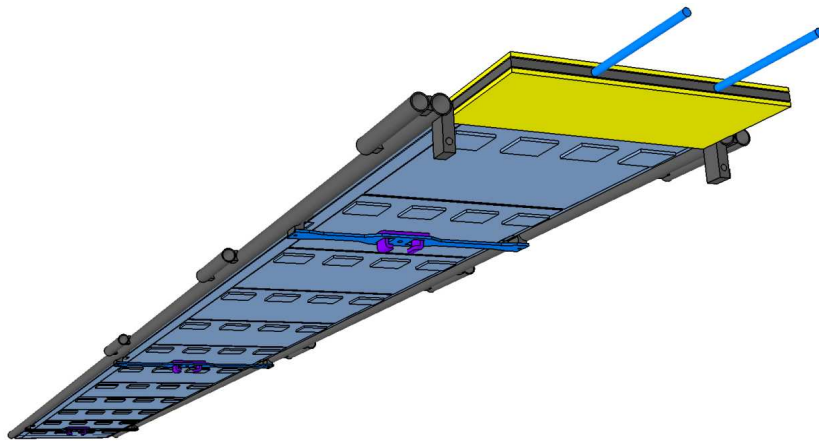
Looking back to current SCT...

- No individual module fixation onto barrel
- A structure to hold a row of modules
- the **End Insertion** is the key point of the developments

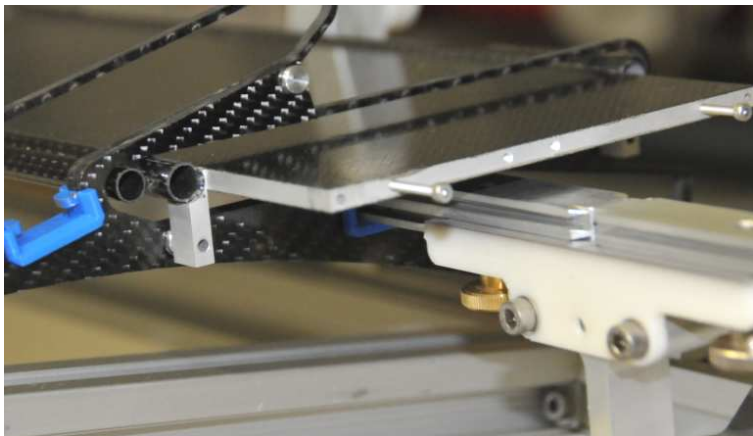


- 2 approaches in parallel to hold 12 modules (or more...): **Staves & SuperModules**
 - Self supporting structure to be assembled / inserted into barrels (5 barrels)
 - Independent part including Modules, Services, and its own Cooling
 - to be assembled after barrel assembly
 - Replacement at any moment (thanks to End Insertion)

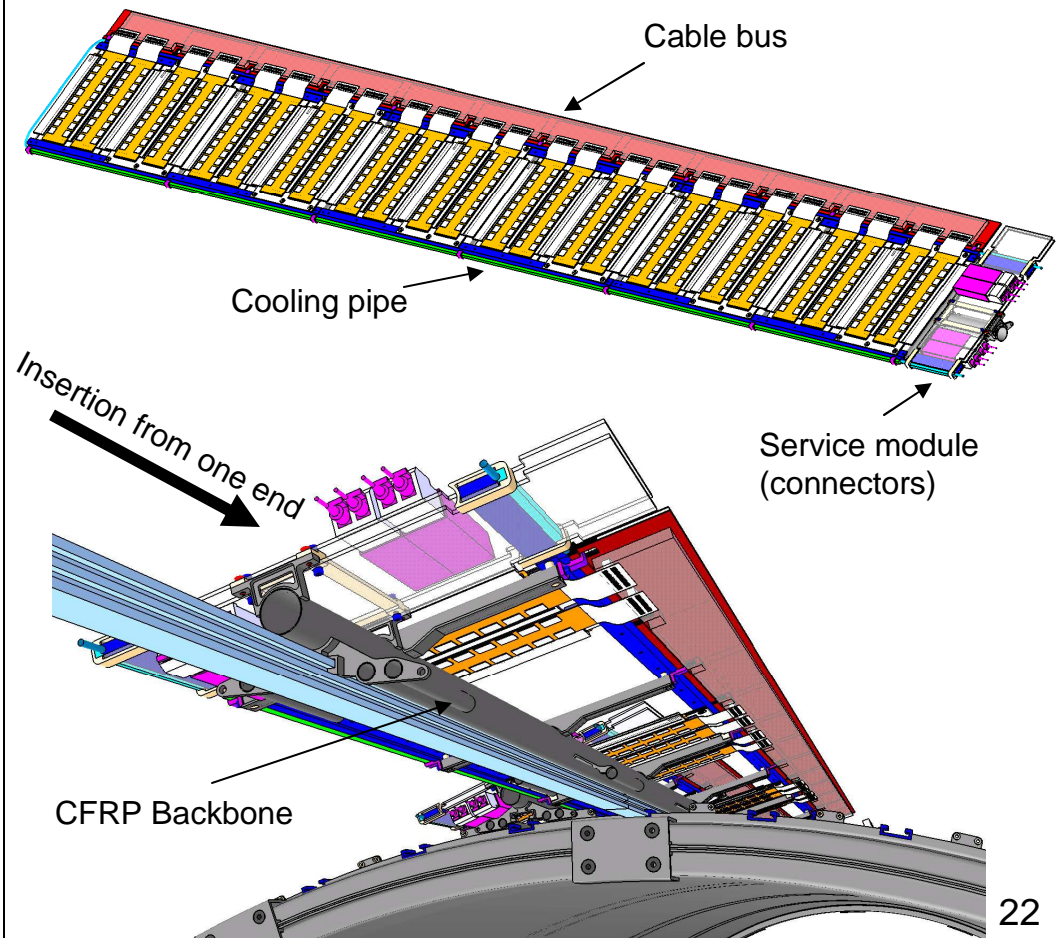
Stave approach



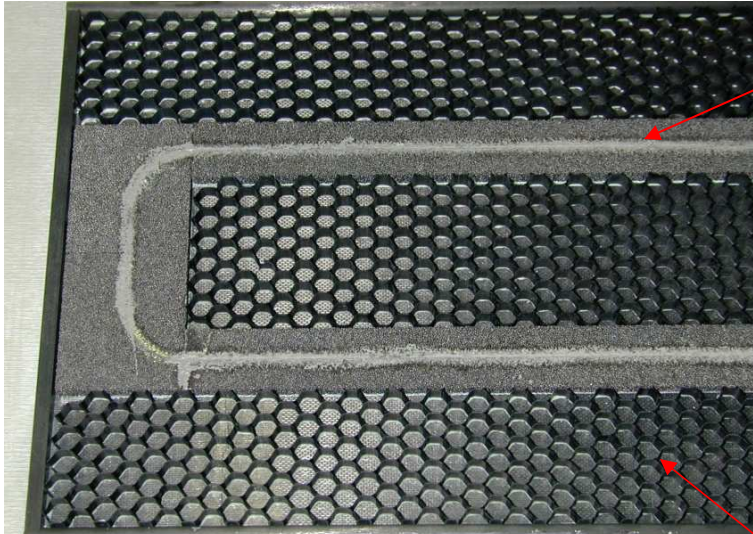
A kind of sandwich plate,
double sided with modules...see next



SuperModule approach



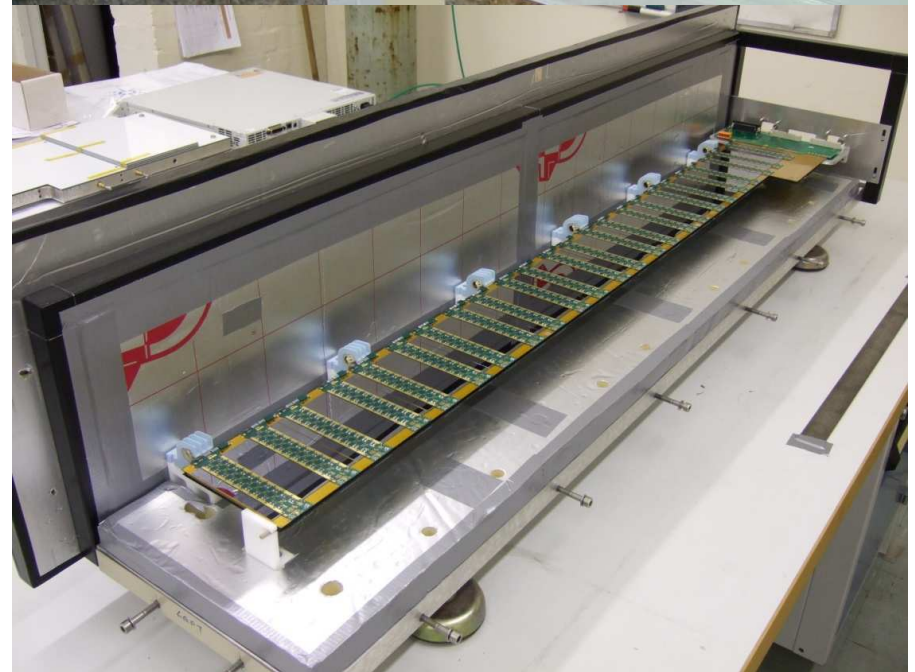
- **Stave** program is being developed in several places (UK, US, ...) to solve:
 - Assembly procedure of the main core (thermal foam, honeycomb, facing, the way to cure)
 - Cable bus bonding to stave
 - Module loading to guarantee the targeted precision
 - Locking mechanism coupled with end insertion



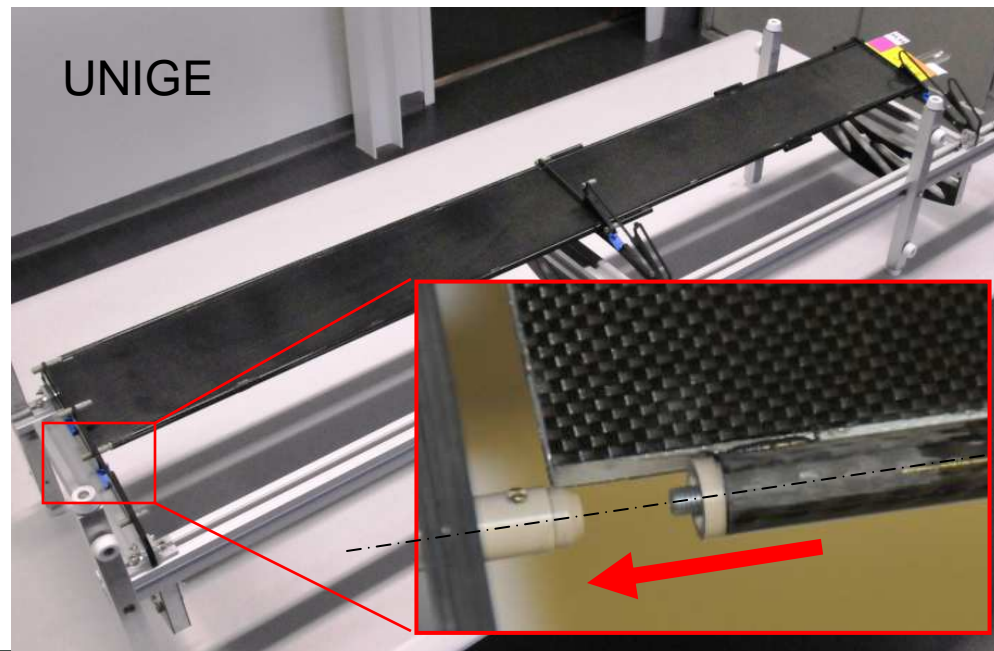
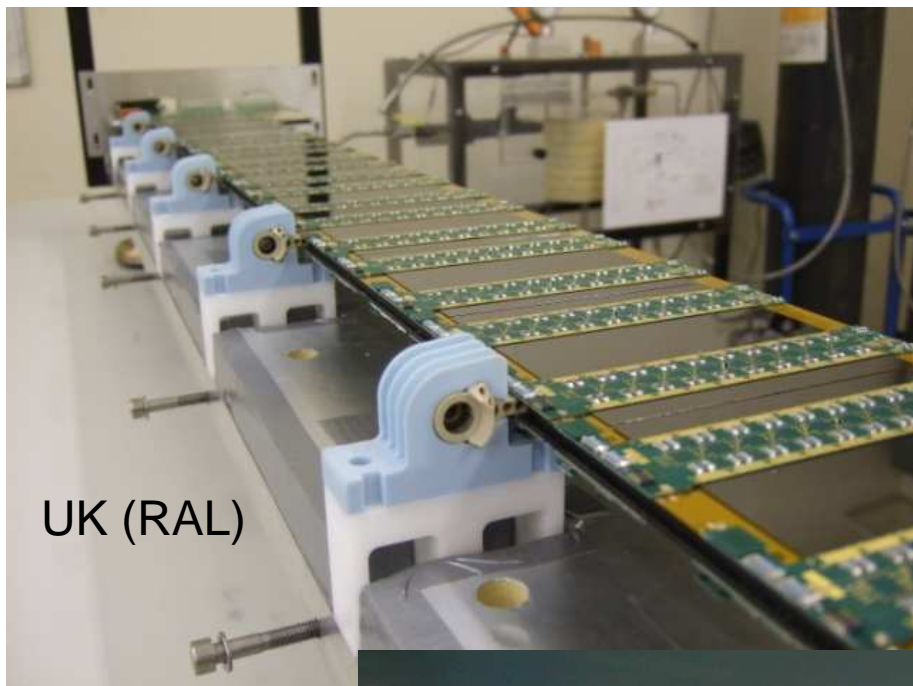
Allcomp foam
(for cooling spreading) +
Cooling pipe
(drives the stave
thickness)



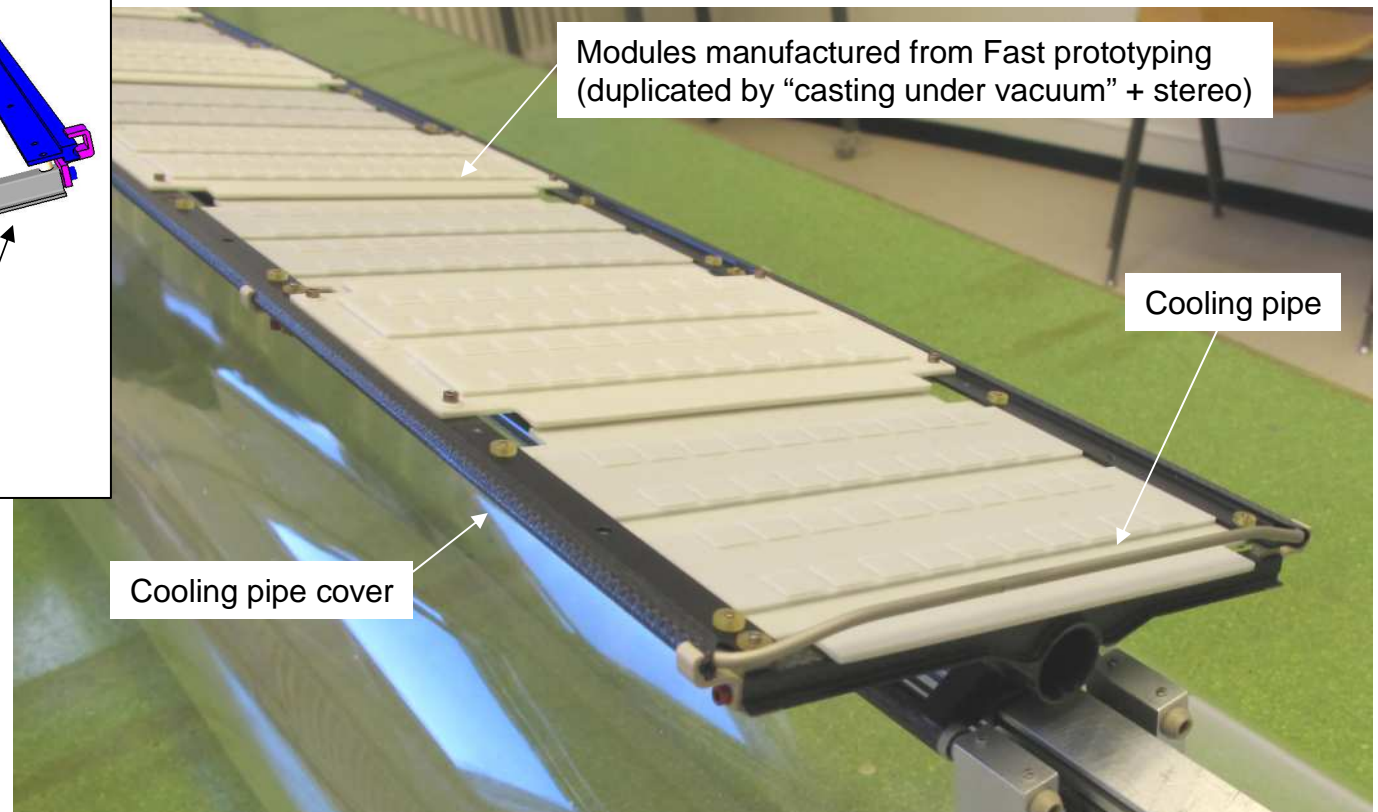
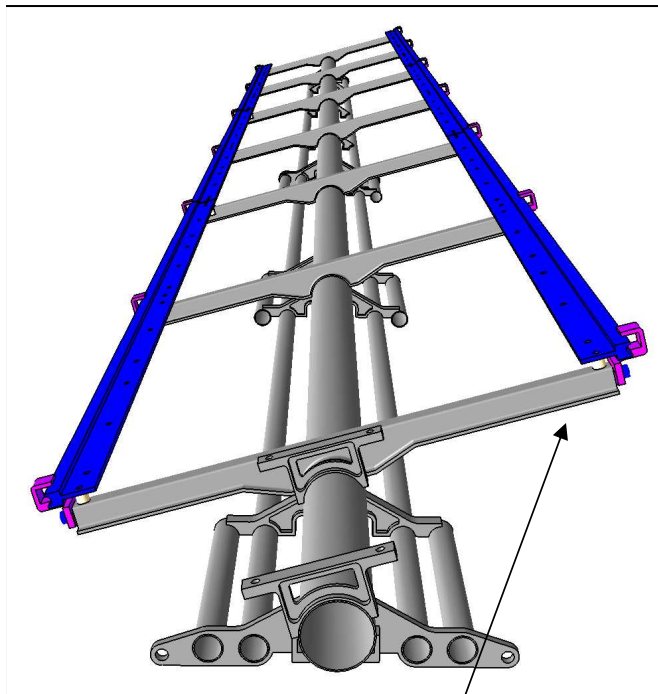
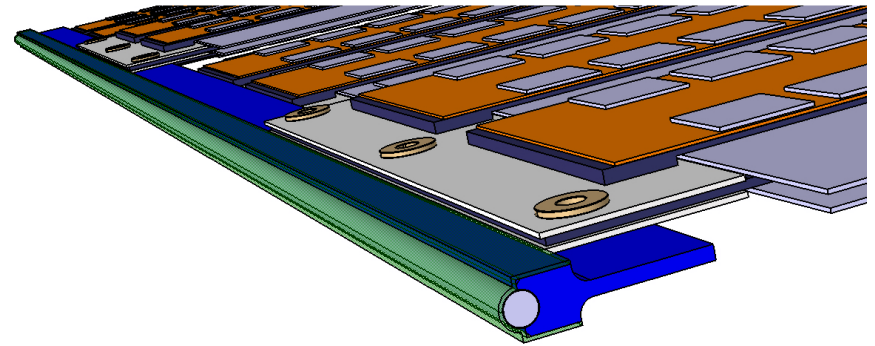
CFRP
Honeycomb



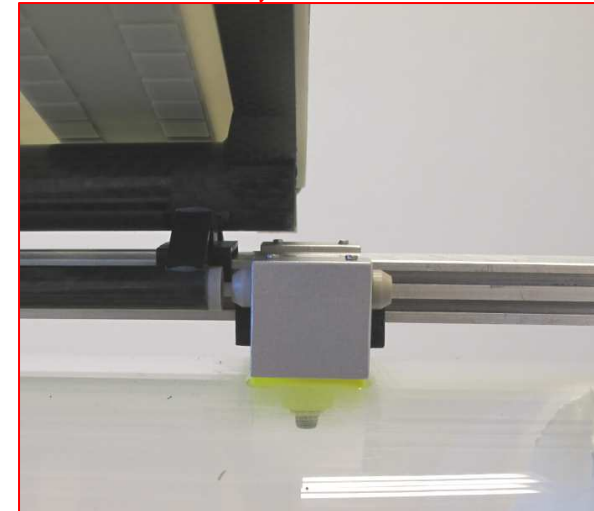
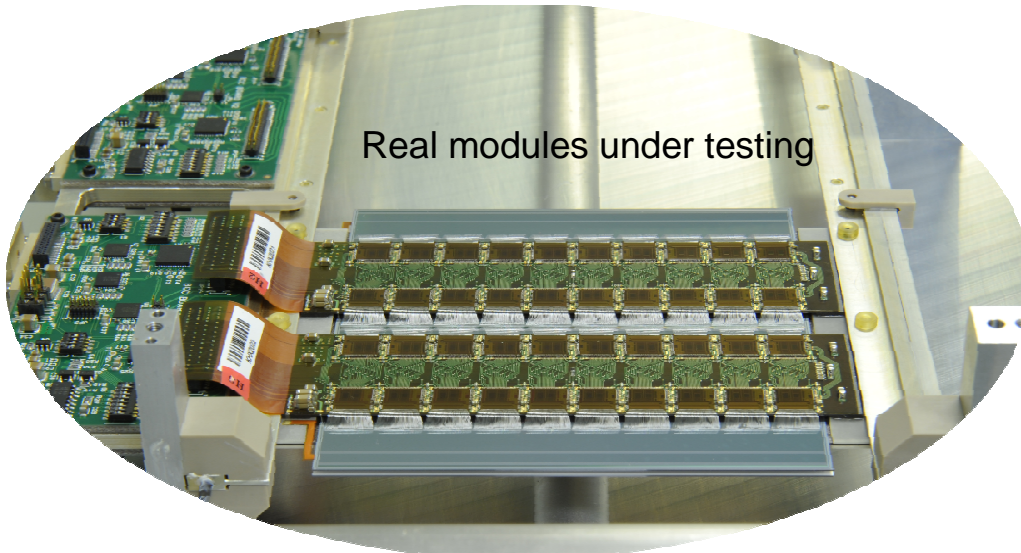
➤ **Stave** locking mechanism to barrels: several approaches under prototyping



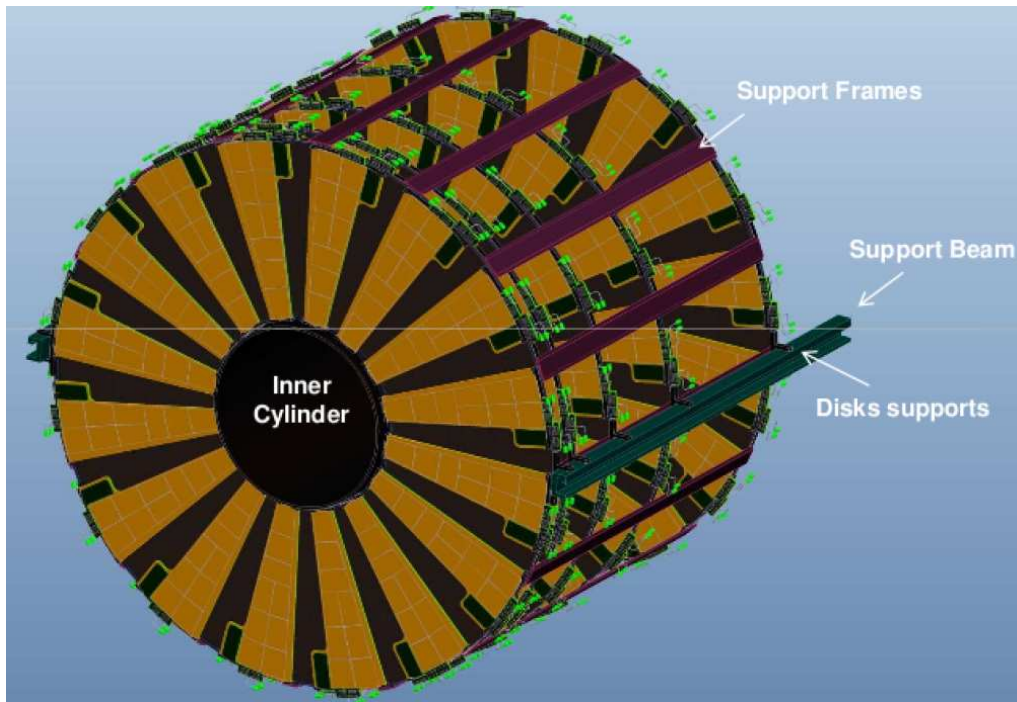
- **Super Module (SM)** program developed in UNIGE and KEK
 - a sort of backbone in CFRP which holds the modules thru cooling plates
 - overall thickness independent on cooling pipe size (choice of coolant can be done late)
 - Cable bus on one side of the SM
 - amount of glue is limited (no foam used)
 - Modularity at the level of modules (sensor and Front End)



- **SuperModule** locking mechanism to barrels on 3 points



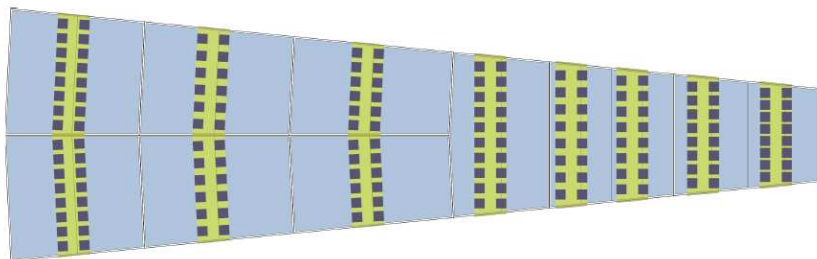
- **End Cap Stave (petal)**
 - very close design to STRIP Stave (common developments)



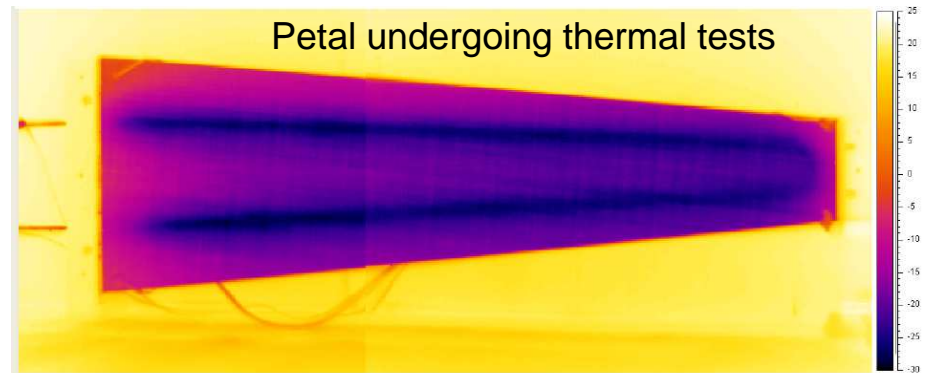
Petal undergoing metrology in Valencia



Petal shape and sensor layout



Petal undergoing thermal tests



The question is more about “**how to better use the existing technology**”...
than discovering new ones (we have tools available)
Both on Atlas or AMS, the need to use a fully integrated system (electronics, CAD)
is (or was) real...
For instance, we paid a lot on AMS-02 of thinking about services a bit too late...!

It seems that the approach used on the Upgrades is going to the right direction,
the issues about integration, services, cooling is tackled soon in the design!
It should help defining the interfaces